

CPC COOPERATIVE PATENT CLASSIFICATION

H05K PRINTED CIRCUITS; CASINGS OR CONSTRUCTIONAL DETAILS OF ELECTRIC APPARATUS; MANUFACTURE OF ASSEMBLAGES OF ELECTRICAL COMPONENTS (details of instruments or comparable details of other apparatus not otherwise provided for [G12B](#); thin-film or thick-film circuits [H01L 27/01](#), [H01L 27/13](#); non-printed means for electric connections to or between printed circuits, {electric connections or line connectors, apparatus or processes for manufacturing, assembling, maintaining or repairing such connections or connectors} [H01R](#); casings for, or constructional details of, particular types of apparatus, [see the relevant subclasses](#); processes involving only a single technical art, e.g. heating, spraying, for which provision exists elsewhere, [see the relevant classes](#))

NOTES

1. This subclass [covers](#):
 - combinations of a radio or television receiver with apparatus having a different main function;
 - printed circuits structurally associated with non-printed electric components;
 - {printed connectors (non printed connectors [H01R](#))}
2. In this subclass, the following expression is used with the meaning indicated:
 - "printed circuits" covers all kinds of mechanical constructions of circuits that consist of an insulating base or support carrying the conductor and are combined structurally with the conductor throughout their length, especially in a two-dimensional plane, the conductors of which are secured to the base in a non-dismountable manner, and also covers the processes or apparatus for manufacturing such constructions, e.g. forming the circuit by mechanical or chemical treatment of a conductive foil, paste, or film on an insulating support.

1/00	Printed circuits (assemblies of a plurality of individual semiconductor or solid state devices H01L 25/00 ; devices consisting of a plurality of solid state components formed in or on a common substrate, e.g. integrated circuits, thin-film or thick-film circuits, H01L 27/00)	1/0218 {by printed shielding conductors, ground planes or power plane (H05K 1/0236 takes precedence)}
1/02	. Details	1/0219 {Printed shielding conductors for shielding around or between signal conductors, e.g. coplanar or coaxial printed shielding conductors}
1/0201	. . {Thermal arrangements, e.g. for cooling, heating or preventing overheating}	1/0221 {Coaxially shielded signal lines comprising a continuous shielding layer partially or wholly surrounding the signal lines (coaxially shielded vias H05K 1/0222)}
1/0203	. . . {Cooling of mounted components (H05K 1/0272 takes precedence)}	1/0222 {for shielding around a single via or around a group of vias, e.g. coaxial vias or vias surrounded by a grounded via fence}
1/0204 {using means for thermal conduction connection in the thickness direction of the substrate (H05K 1/0207 takes precedence)}	1/0224 {Patterned shielding planes, ground planes or power planes (H05K 1/0253 takes precedence)}
1/0206 {by printed thermal vias}	1/0225 {Single or multiple openings in a shielding, ground or power plane (H05K 1/0227 takes precedence)}
1/0207 {using internal conductor planes parallel to the surface for thermal conduction, e.g. power planes}	1/0227 {Split or nearly split shielding or ground planes}
1/0209 {External configuration of printed circuit board adapted for heat dissipation, e.g. lay-out of conductors, coatings}	1/0228 {Compensation of cross-talk by a mutually correlated lay-out of printed circuit traces, e.g. for compensation of cross-talk in mounted connectors (balanced signal pairs H05K 1/0245)}
1/021 {Components thermally connected to metal substrates or heat-sinks by insert mounting}	1/023 {using auxiliary mounted passive components or auxiliary substances (printed passive components H05K 1/16)}
1/0212	. . . {Printed circuits or mounted components having integral heating means}	1/0231 {Capacitors or dielectric substances}
1/0213	. . {Electrical arrangements not otherwise provided for (screening H05K 9/00 ; emergency protective circuits H02H)}	1/0233 {Filters, inductors or a magnetic substance}
1/0215	. . . {Grounding of printed circuits by connection to external grounding means}		
1/0216	. . . {Reduction of cross-talk, and noise or electromagnetic interference (grounding H05K 1/0215)}		

- 1/0234 {Resistors or by disposing resistive or lossy substances in or near power planes ([H05K 1/0246](#) takes precedence)}
- 1/0236 {Electromagnetic band-gap structures (conductive planes with an opening or a split [H05K 1/0225](#), [H05K 1/0227](#))}
- 1/0237 . . . {High frequency adaptations ([H05K 1/0216](#) takes precedence)}
- 1/0239 {Signal transmission by AC coupling}
- 1/024 {Dielectric details, e.g. changing the dielectric material around a transmission line}
- 1/0242 {Structural details of individual signal conductors, e.g. related to the skin effect}
- 1/0243 {Printed circuits associated with mounted high frequency components}
- 1/0245 {Lay-out of balanced signal pairs, e.g. differential lines or twisted lines}
- 1/0246 {Termination of transmission lines}
- 1/0248 {Skew reduction or using delay lines}
- 1/025 {Impedance arrangements, e.g. impedance matching, reduction of parasitic impedance ([H05K 1/024](#) and [H05K 1/0243](#) take precedence; for semiconductor devices [H01L 23/66](#))}
- 1/0251 {related to vias or transitions between vias and transmission lines}
- 1/0253 {Impedance adaptations of transmission lines by special lay-out of power planes, e.g. providing openings ([H05K 1/0251](#) takes precedence)}
- 1/0254 . . . {High voltage adaptations; Electrical insulation details; Overvoltage or electrostatic discharge protection (electrostatic discharge protection for electric apparatus in general [H05K 9/0067](#), [H05K 9/0079](#)); Arrangements for regulating voltages or for using plural voltages}
- 1/0256 {Electrical insulation details, e.g. around high voltage areas}
- 1/0257 {Overvoltage protection}
- 1/0259 {Electrostatic discharge [ESD] protection}
- 1/026 {Spark gaps ([spark gaps per se H01T](#))}
- 1/0262 {Arrangements for regulating voltages or for using plural voltages}
- 1/0263 . . . {High current adaptations, e.g. printed high current conductors or using auxiliary non-printed means; Fine and coarse circuit patterns on one circuit board ([H05K 1/0293](#) takes precedence)}
- 1/0265 {characterized by the lay-out of or details of the printed conductors, e.g. reinforced conductors, redundant conductors, conductors having different cross-sections}
- 1/0266 . . {Marks, test patterns, inspection means or identification means}
- 1/0268 . . . {for electrical inspection or testing}
- 1/0269 . . . {for visual or optical inspection}
- 1/0271 . . {Arrangements for reducing stress or warp in rigid printed circuit boards, e.g. caused by loads, vibrations or differences in thermal expansion}
- 1/0272 . . {Adaptations for fluid transport, e.g. channels, holes}
- 1/0274 . . {Optical details, e.g. printed circuits comprising integral optical means ([H05K 1/0269](#) takes precedence; Coupling light guides with optoelectronic components [G02B 6/42](#))}
- 1/0275 . . {Security details, e.g. tampering prevention or detection (security details of computer components [G06F 21/70](#))}
- 1/0277 . . {Bendability or stretchability details (not used, see subgroups; [H05K 1/038](#), [H05K 3/4691](#) take precedence)}
- 1/0278 . . . {Rigid circuit boards or rigid supports of circuit boards locally made bendable, e.g. by removal or replacement of material}
- 1/028 . . . {Bending or folding regions of flexible printed circuits ([H05K 1/0283](#) takes precedence)}
- 1/0281 {Reinforcement details thereof}
- 1/0283 . . . {Stretchable printed circuits}
- 1/0284 . . {Details of three-dimensional rigid printed circuit boards ([H05K 1/119](#) takes precedence; shaping of the substrate [H05K 3/0014](#))}
- 1/0286 . . {Programmable, customizable or modifiable circuits (by programmable non-printed jumper connections [H05K 3/222](#))}
- 1/0287 . . . {having an universal lay-out, e.g. pad or land grid patterns or mesh patterns}
- 1/0289 {having a matrix lay-out, i.e. having selectively interconnectable sets of X-conductors and Y-conductors in different planes}
- 1/029 . . . {having a programmable lay-out, i.e. adapted for choosing between a few possibilities}
- 1/0292 . . . {having a modifiable lay-out, i.e. adapted for engineering changes or repair ([H05K 1/0293](#) takes precedence)}
- 1/0293 . . . {Individual printed conductors which are adapted for modification, e.g. fusable or breakable conductors, printed switches}
- 1/0295 . . . {adapted for choosing between different types or different locations of mounted components}
- 1/0296 . . {Conductive pattern lay-out details not covered by sub groups [H05K 1/02](#) - [H05K 1/0295](#) ([H05K 1/11](#) takes precedence; lay-out adapted to mounted component configuration [H05K 1/18](#))}
- 1/0298 . . . {Multilayer circuits}
- 1/03 . . Use of materials for the substrate {(substrates for semiconductor chips [H01L 23/00](#))}
- 1/0306 . . . {Inorganic insulating substrates, e.g. ceramic, glass}
- 1/0313 . . . {Organic insulating material}
- 1/032 {consisting of one material}
- NOTE**
- In this group, in the absence of an indication to the contrary, a material is classified in the last appropriate place
- 1/0326 {containing O}
- 1/0333 {containing S}
- 1/034 {containing halogen}
- 1/0346 {containing N}
- 1/0353 {consisting of two or more materials, e.g. two or more polymers, polymer + filler, + reinforcement}
- 1/036 {Multilayers with layers of different types}

- 1/0366 {reinforced, e.g. by fibres, fabrics
([H05K 1/036](#) takes precedence)}
- 1/0373 {containing additives, e.g. fillers
([H05K 1/036](#) takes precedence)}
- 1/038 . . . {Textiles (used as reinforcing materials for
organic insulating substrates [H05K 1/0366](#))}
- 1/0386 . . . {Paper sheets (used as reinforcing materials for
organic insulating substrates [H05K 1/0366](#))}
- 1/0393 . . . {Flexible materials ([H05K 1/038](#) takes
precedence; specific organic compositions are
classified in [H05K 1/0313](#) and subgroups)}
- 1/05 . . . Insulated metal substrate {or other insulated
electrically conductive substrate (thermal
coupling of mounted components and metal
substrate [H05K 1/0204](#), [H05K 1/021](#))}
- 1/053 {the metal substrate being covered by an
inorganic insulating layer}
- 1/056 {the metal substrate being covered by an
organic insulating layer}
- 1/09 . . Use of materials for the metallic pattern {or other
conductive pattern (materials for conductors
[H01B 1/00](#))}
- 1/092 . . . {Dispersed materials, e.g. conductive pastes
or inks (Conductive material dispersed
in non-conductive material in general
[H01B 1/14](#) - [H01B 1/24](#); Conductive inks in
general [C09D 11/52](#))}
- 1/095 {for polymer thick films, i.e. having a
permanent organic polymeric binder}
- 1/097 {Inks comprising nanoparticles, i.e. inks
which are sinterable at low temperatures}
- 1/11 . . Printed elements for providing electric
connections to or between printed circuits
- 1/111 {Pads for surface mounting, e.g. lay-out}
- 1/112 {directly combined with via connections}
- 1/113 {Via provided in pad; Pad over filled via}
- 1/114 {Pad being close to via, but not
surrounding the via}
- 1/115 . . . {Via connections; Lands around holes or via
connections ([H05K 1/112](#) takes precedence)}
- 1/116 {Lands, clearance holes or other lay-out
details concerning the surrounding of a via}
- 1/117 . . . {Pads along the edge of rigid circuit boards,
e.g. for pluggable connectors}
- 1/118 . . . {specially for flexible printed circuits, e.g.
using folded portions}
- 1/119 . . . {Details of rigid insulating substrates therefor,
e.g. three-dimensional details ([H05K 1/117](#)
takes precedence)}
- 1/14 . . Structural association of two or more printed
circuits (providing electric connection to or
between printed circuits [H05K 1/11](#), [H01R 9/09](#),
[H01R 23/68](#))
- 1/141 . . . {One or more single auxiliary printed
circuits mounted on a main printed circuit,
e.g. modules, adapters ([H05K 1/142](#) and
[H05K 1/147](#) take precedence)}
- 1/142 . . . {Arrangements of planar printed circuit boards
in the same plane, e.g. auxiliary printed circuit
insert mounted in a main printed circuit}
- 1/144 . . . {Stacked arrangements of planar printed circuit
boards}
- 1/145 . . . {Arrangements wherein electric components
are disposed between and simultaneously
connected to two planar printed circuit boards,
e.g. Cordwood modules}
- 1/147 . . . {at least one of the printed circuits being bent
or folded, e.g. by using a flexible printed circuit
([H05K 1/148](#) takes precedence)}
- 1/148 . . . {Arrangements of two or more hingeably
connected rigid printed circuit boards, i.e.
connected by flexible means}
- 1/16 . . incorporating printed electric components, e.g.
printed resistor, capacitor, inductor {(thick-film or
thin-film circuits [H01L 27/01](#), [H01L 27/13](#))}
- 1/162 . . {incorporating printed capacitors}
- 1/165 . . {incorporating printed inductors}
- 1/167 . . {incorporating printed resistors}
- 1/18 . . Printed circuits structurally associated with non-
printed electric components ({[H05K 1/0201](#),
[H05K 1/023](#), [H05K 1/0243](#), } [H05K 1/16](#) take
precedence)}
- 1/181 . . {associated with surface mounted components}
- 1/182 . . {associated with components mounted in the
printed circuit board, e.g. IMC (insert mounted
components)}
- 1/183 . . . {Components mounted in and supported by
recessed areas of the printed circuit board}
- 1/184 . . . {Components including terminals inserted in
holes through the printed circuit board and
connected to printed contacts on the walls of
the holes or at the edges thereof or protruding
over or into the holes}
- 1/185 . . . {Components encapsulated in the insulating
substrate of the printed circuit or incorporated
in internal layers of a multilayer circuit
(semiconductor chips encapsulated by
interconnect and support structures
[H01L 23/5389](#), [H01L 24/00](#))}
- 1/186 {manufactured by mounting on or
connecting to patterned circuits before or
during embedding}
- 1/187 {the patterned circuits being prefabricated
circuits, which are not yet attached to a
permanent insulating substrate, e.g. on a
temporary carrier}
- 1/188 {manufactured by mounting on or attaching
to a structure having a conductive layer,
e.g. a metal foil, such that the terminals of
the component are connected to or adjacent
to the conductive layer before embedding,
and by using the conductive layer, which is
patterned after embedding, at least partially
for connecting the component}
- 1/189 . . {characterised by the use of a flexible or folded
printed circuit ([H05K 3/326](#) takes precedence)}
- 3/00 Apparatus or processes for manufacturing printed
circuits (photomechanical production of textured or
patterned surfaces, materials or originals therefor,
apparatus specially adapted therefor, in general [G03F](#);
involving the manufacture of semiconductor devices
[H01L](#))**
- 3/0002 . . {for manufacturing artworks for printed circuits}
- 3/0005 . . {for designing circuits by computer}

- 3/0008 . {for aligning or positioning of tools relative to the circuit board ([H05K 3/4638](#), [H05K 3/4679](#) take precedence; for manufacturing assemblages of components [H05K 13/0015](#))}
- 3/0011 . {Working of insulating substrates or insulating layers (making copper-clad substrates [H05K 3/022](#); surface treatment for improvement of adhesion [H05K 3/381](#))}
- 3/0014 . . {Shaping of the substrate, e.g. by moulding}
- 3/0017 . . {Etching of the substrate by chemical or physical means}
- 3/002 . . . {by liquid chemical etching}
- 3/0023 . . . {by exposure and development of a photosensitive insulating layer}
- 3/0026 . . . {by laser ablation}
- 3/0029 {of inorganic insulating material}
- 3/0032 {of organic insulating material}
- 3/0035 {of blind holes, i.e. having a metal layer at the bottom}
- 3/0038 {combined with laser drilling through a metal layer}
- 3/0041 . . . {by plasma etching}
- 3/0044 . . {Mechanical working of the substrate, e.g. drilling or punching ([H05K 3/0008](#) takes precedence)}
- 3/0047 . . . {Drilling of holes}
- 3/005 . . . {Punching of holes}
- 3/0052 . . . {Depaneling, i.e. dividing a panel into circuit boards; Working of the edges of circuit boards}
- 3/0055 . . {After-treatment, e.g. cleaning or desmearing of holes}
- 3/0058 . {Laminating printed circuit boards onto other substrates, e.g. metallic substrates ([H05K 1/0281](#) takes precedence)}
- 3/0061 . . {onto a metallic substrate, e.g. a heat sink (heat sinks for electric apparatus [H05K 7/20](#))}
- 3/0064 . . {onto a polymeric substrate}
- 3/0067 . . {onto an inorganic, non-metallic substrate}
- 3/007 . {Manufacture or processing of a substrate for a printed circuit board supported by a temporary or sacrificial carrier ([H05K 1/187](#), [H05K 3/20](#) and [H05K 3/4682](#) take precedence)}
- 3/0073 . {Masks not provided for in groups [H05K 3/02](#) - [H05K 3/46](#), e.g. for photomechanical production of patterned surfaces}
- 3/0076 . . {characterised by the composition of the mask}
- 3/0079 . . {characterised by the method of application or removal of the mask ([H05K 3/0091](#) takes precedence)}
- 3/0082 . . {characterised by the exposure method of radiation-sensitive masks}
- 3/0085 . {Apparatus for treatments of printed circuits with liquids not provided for in groups [H05K 3/02](#) - [H05K 3/46](#); conveyors and holding means therefor (apparatus specially adapted for manufacturing assemblages of electric components, e.g. printed circuit boards, [H05K 13/00](#))}
- 3/0088 . . {for treatment of holes}
- 3/0091 . {Apparatus for coating printed circuits using liquid non-metallic coating compositions}
- 3/0094 . {Filling or covering plated through-holes or blind plated vias, e.g. for masking or for mechanical reinforcement}
- 3/0097 . {Processing two or more printed circuits simultaneously, e.g. made from a common substrate, or temporarily stacked circuit boards ([H05K 3/0052](#) takes precedence)}
- 3/02 . in which the conductive material is applied to the surface of the insulating support and is thereafter removed from such areas of the surface which are not intended for current conducting or shielding
- 3/022 . . {Processes for manufacturing precursors of printed circuits, i.e. copper-clad substrates (laminates in general [B32B](#))}
- 3/025 . . . {by transfer of thin metal foil formed on a temporary carrier, e.g. peel-apart copper}
- 3/027 . . {the conductive material being removed by irradiation, e.g. by photons, alpha, beta particles (machining by laser in general [B23K 26/00](#); electron - or ion beam tubes therefor [H01J 37/00](#))}
- 3/04 . . the conductive material being removed mechanically, e.g. by punching
- 3/041 . . . {by using a die for cutting the conductive material}
- 3/043 . . . {by using a moving tool for milling or cutting the conductive material}
- 3/045 . . . {by making a conductive layer having a relief pattern, followed by abrading of the raised portions}
- 3/046 . . . {by selective transfer or selective detachment of a conductive layer}
- 3/048 {using a lift-off resist pattern or a release layer pattern}
- 3/06 . . the conductive material being removed chemically or electrolytically, e.g. by photo-etch process {(Non-mechanical removal of metallic material from surfaces [C23F](#); semi-additive methods [H05K 3/108](#))}
- 3/061 . . . {Etching masks (local etching [C23F 1/02](#))}
- 3/062 {consisting of metals or alloys or metallic inorganic compounds ([H05K 3/065](#) takes precedence)}
- 3/064 {Photoresists}
- 3/065 {applied by electrographic, electrophotographic or magnetographic methods (in general [G03G](#))}
- 3/067 . . . {Etchants (in general [C23F 1/10](#) - [C23F 1/46](#))}
- 3/068 . . . {Apparatus for etching printed circuits (in general [C23F 1/08](#))}
- 3/07 . . . being removed electrolytically
- 3/08 . . the conductive material being removed by electric discharge, e.g. by spark erosion {(working of metal by electro-erosion *per se* [B23H](#))}
- 3/10 . in which conductive material is applied to the insulating support in such a manner as to form the desired conductive pattern
- 3/101 . . {by casting or moulding of conductive material}
- 3/102 . . {by bonding of conductive powder, i.e. metallic powder ([H05K 3/12](#) takes precedence)}
- 3/103 . . {by bonding or embedding conductive wires or strips}
- 3/105 . . {by conversion of non-conductive material on or in the support into conductive material, e.g. by using an energy beam}
- 3/106 . . . {by photographic methods (in general [G03C](#))}

- 3/107 . . {by filling grooves in the support with conductive material ([H05K 3/045](#), [H05K 3/101](#), [H05K 3/1258](#) and [H05K 3/465](#) take precedence)}
- 3/108 . . {by semi-additive methods; masks therefor (characterised by metallic etch mask [H05K 3/062](#); electroplating methods or apparatus [H05K 3/241](#))}
- 3/12 . . using {thick film techniques, e.g.} printing techniques to apply the conductive material {or similar techniques for applying conductive paste or ink patterns (printing techniques in general [B41M](#), printing apparatus [B41F](#))}
- 3/1208 . . . {Pretreatment of the circuit board, e.g. modifying wetting properties; Patterning by using affinity patterns (providing shape patterns [H05K 3/1258](#); adhesion treatments [H05K 3/38](#))}
- 3/1216 . . . {by screen printing or stencil printing}
- 3/1225 {Screens or stencils (in general [B41N 1/24](#); manufacturing of screens or stencils [B41C 1/14](#); Holders therefor (stencil holders for applying liquids [B05C 17/08](#))}
- 3/1233 {Methods or means for supplying the conductive material and for forcing it through the screen or stencil}
- 3/1241 . . . {by ink-jet printing or drawing by dispensing}
- 3/125 {by ink-jet printing (in general [B41J](#))}
- 3/1258 . . . {by using a substrate provided with a shape pattern, e.g. grooves, banks, resist pattern}
- 3/1266 . . . {by electrographic or magnetographic printing (in general [G03G](#))}
- 3/1275 . . . {by other printing techniques, e.g. letterpress printing, intaglio printing, lithographic printing, offset printing}
- 3/1283 . . . {After-treatment of the printed patterns, e.g. sintering or curing methods}
- 3/1291 {Firing or sintering at relative high temperatures for patterns on inorganic boards, e.g. co-firing of circuits on green ceramic sheets}
- 3/14 . . using spraying techniques to apply the conductive material {including vapour evaporation; (covering metals by metal spraying [C23C 4/00](#); coating by vacuum evaporation [C23C 14/00](#))}
- 3/143 . . . {Masks therefor ([H05K 3/048](#) takes precedence)}
- 3/146 . . . {By vapour deposition}
- 3/16 . . . by cathodic sputtering {(covering materials by cathodic sputtering [C23C 14/34](#); discharge devices therefor [H01J 37/34](#))}
- 3/18 . . using precipitation techniques to apply the conductive material {(chemical coating of a substrate by decomposition [C23C 18/00](#))}
- 3/181 . . . {by electroless plating (adhesives therefor [H05K 3/387](#); electroless plating in general [C23C 18/16](#))}
- 3/182 {characterised by the patterning method}
- 3/184 {using masks}
- 3/185 {by making a catalytic pattern by photo-imaging}
- 3/187 {means therefor, e.g. baths, apparatus}
- 3/188 . . . {by direct electroplating}
- 3/20 . . by affixing prefabricated conductor pattern {(H05K 1/187, [H05K 3/046](#), [H05K 3/4658](#), [H05K 3/4682](#) takes precedence)}
- 3/202 . . . {using self-supporting metal foil pattern}
- 3/205 . . . {using a pattern electroplated or electroformed on a metallic carrier}
- 3/207 . . . {using a prefabricated paste pattern, ink pattern or powder pattern}
- 3/22 . Secondary treatment of printed circuits {(H05K 3/1283 takes precedence; embedding circuits in grooves by pressure [H05K 3/107](#))}
- 3/222 . . {Completing of printed circuits by adding non-printed jumper connections (printed jumper connections [H05K 3/4685](#))}
- 3/225 . . {Correcting or repairing of printed circuits ([H05K 1/0292](#), [H05K 3/222](#), [H05K 3/288](#), [H05K 3/4685](#) take precedence)}
- 3/227 . . {Drying of printed circuits}
- 3/24 . . Reinforcing the conductive pattern {(by solder coating [H05K 3/3457](#))}
- 3/241 . . . {characterised by the electroplating method; means therefor, e.g. baths, apparatus (electroplating in general [C25D](#))}
- 3/242 {characterised by using temporary conductors on the printed circuit for electrically connecting areas which are to be electroplated}
- 3/243 . . . {characterised by selective plating, e.g. for finish plating of pads (selective plating for making the circuit pattern [H05K 3/108](#), [H05K 3/182](#))}
- 3/244 . . . {Finish plating of conductors, especially of copper conductors, e.g. for pads or lands (selective plating methods [H05K 3/243](#); finish plating of conductors made by printing techniques [H05K 3/246](#); solder as finish [H05K 3/3457](#), e.g. by plating [H05K 3/3473](#))}
- 3/245 . . . {Reinforcing conductive patterns made by printing techniques or by other techniques for applying conductive pastes, inks or powders; Reinforcing other conductive patterns by such techniques}
- 3/246 {Reinforcing conductive paste, ink or powder patterns by other methods, e.g. by plating}
- 3/247 {Finish coating of conductors by using conductive pastes, inks or powders}
- 3/248 {fired compositions for inorganic substrates}
- 3/249 {comprising carbon particles as main constituent}
- 3/26 . . Cleaning or polishing of the conductive pattern
- 3/28 . . Applying non-metallic protective coatings {(H05K 3/0091 takes precedence; methods for intermediate insulating layers for build-up multilayer circuits [H05K 3/4673](#))}
- 3/281 . . . {by means of a preformed insulating foil ([H05K 3/284](#) takes precedence)}
- 3/282 . . . {for inhibiting the corrosion of the circuit, e.g. for preserving the solderability}
- 3/284 . . . {for encapsulating mounted components ([H05K 1/185](#) takes precedence)}
- 3/285 . . . {Permanent coating compositions}
- 3/287 {Photosensitive compositions}
- 3/288 . . . {Removal of non-metallic coatings, e.g. for repairing}
- 3/30 . Assembling printed circuits with electric components, e.g. with resistor

- 3/301 . . {by means of a mounting structure ([H05K 3/325 takes precedence](#))}
- 3/303 . . {Surface mounted components, e.g. affixing before soldering, aligning means, spacing means ([H05K 3/32 takes precedence](#))}
- 3/305 . . . {Affixing by adhesive}
- 3/306 . . {Lead-in-hole components, e.g. affixing or retention before soldering, spacing means ([H05K 3/32 takes precedence](#))}
- 3/308 . . . {Adaptations of leads ([connectors to printed circuits H01R 9/091](#))}
- 3/32 . . electrically connecting electric components or wires to printed circuits
- 3/321 . . . {by conductive adhesive ([in general H01R 4/04](#))}
- 3/323 {by applying an anisotropic conductive adhesive layer over an array of pads}
- 3/325 . . . {by abutting or pinching, i.e. without alloying process; mechanical auxiliary parts therefor ([adaptations of leads inserted in holes for press-fit connections H05K 3/308](#))}
- 3/326 {the printed circuit having integral resilient or deformable parts, e.g. tabs or parts of flexible circuits ([H05K 3/365 takes precedence](#))}
- 3/328 . . . {by welding}
- 3/34 . . . by soldering ([soldering or desoldering apparatus H05K 13/04, B23K 1/00, B23K 3/00](#))}
- 3/3405 {Edge mounted components, e.g. terminals}
- 3/341 {Surface mounted components}
- 3/3415 {on both sides of the substrate or combined with lead-in-hole components}
- 3/3421 {Leaded components}
- 3/3426 {characterised by the leads}
- 3/3431 {Leadless components}
- 3/3436 {having an array of bottom contacts, e.g. pad grid array or ball grid array components}
- 3/3442 {having edge contacts, e.g. leadless chip capacitors, chip carriers}
- 3/3447 {Lead-in-hole components ([H05K 3/3415 takes precedence](#))}
- 3/3452 {Solder masks}
- 3/3457 {Solder materials or compositions ([solder compositions per se B23K 35/24](#)); Methods of application thereof}
- 3/3463 {Solder compositions in relation to features of the printed circuit board or the mounting process}
- 3/3468 {Applying molten solder}
- 3/3473 {Plating of solder}
- 3/3478 {Applying solder paste, particles or preforms; Transferring prefabricated solder patterns}
- 3/3484 {Paste or slurry or powder ([screen printing or stencil printing of solder paste H05K 3/1216](#))}
- 3/3489 {Composition of fluxes; Methods of application thereof; Other methods of activating the contact surfaces}
- 3/3494 {Heating methods for reflowing of solder ([using integral heating means H05K 1/0212](#))}
- 3/36 . . Assembling printed circuits with other printed circuits ([H05K 7/142 takes precedence](#))}
- 3/361 . . {Assembling flexible printed circuits with other printed circuits}
- 3/363 . . . {by soldering}
- 3/365 . . . {by abutting, i.e. without alloying process}
- 3/366 . . {substantially perpendicularly to each other ([H05K 3/361 takes precedence](#))}
- 3/368 . . {parallel to each other ([H05K 3/361 takes precedence](#))}
- 3/38 . . Improvement of the adhesion between the insulating substrate and the metal ([Laminates per se B32B](#))
- 3/381 . . {by special treatment of the substrate}
- 3/382 . . {by special treatment of the metal}
- 3/383 . . . {by microetching}
- 3/384 . . . {by plating}
- 3/385 . . . {by conversion of the surface of the metal, e.g. by oxidation, whether or not followed by reaction or removal of the converted layer}
- 3/386 . . {by the use of an organic polymeric bonding layer, e.g. adhesive}
- 3/387 . . . {for electroless plating ([H05K 3/4661 takes precedence](#))}
- 3/388 . . {by the use of a metallic or inorganic thin film adhesion layer}
- 3/389 . . {by the use of a coupling agent, e.g. silane}
- 3/40 . . Forming printed elements for providing electric connections to or between printed circuits
- 3/4007 . . {Surface contacts, e.g. bumps ([H05K 3/4092 takes precedence](#); deposition of finish layers on pads [H05K 3/24](#); forming solder bumps [H05K 3/3457](#))}
- 3/4015 . . . {using auxiliary conductive elements, e.g. pieces of metal foil, metallic spheres}
- 3/403 . . {Edge contacts; Windows or holes in the substrate having plural connections on the walls thereof ([H05K 3/4092 takes precedence](#))}
- 3/4038 . . {Through-connections or via connections ([H05K 3/403 and H05K 3/42 take precedence](#))}
- 3/4046 . . . {using auxiliary conductive elements, e.g. metallic spheres, eyelets, pieces of wire}
- 3/4053 . . . {by thick-film techniques}
- 3/4061 {for via connections in inorganic insulating substrates}
- 3/4069 {for via connections in organic insulating substrates}
- 3/4076 . . . {by thin-film techniques}
- 3/4084 . . . {by deforming at least one of the conductive layers}
- 3/4092 . . {Integral conductive tabs, i.e. conductive parts partly detached from the substrate}
- 3/42 . . Plated through-holes {or plated via connections}
- 3/421 . . . {Blind plated via connections ([H05K 3/422, H05K 3/423 and H05K 3/425 take precedence](#))}
- 3/422 . . . {characterised by electroless plating method; pretreatment therefor}
- 3/423 . . . {characterised by electroplating method}
- 3/424 {by direct electroplating}
- 3/425 . . . {characterised by the sequence of steps for plating the through-holes or via connections in relation to the conductive pattern}
- 3/426 {initial plating of through-holes in substrates without metal}

- 3/427 {initial plating of through-holes in metal-clad substrates}
- 3/428 {initial plating of through-holes in substrates having a metal pattern}
- 3/429 . . . {Plated through-holes specially for multilayer circuits, e.g. having connections to inner circuit layers}
- 3/44 . Manufacture insulated metal core circuits {or other insulated electrically conductive core circuits ([H05K 3/0058](#), [H05K 3/4641](#), [H05K 3/4608](#) take precedence)}
- 3/445 . . {having insulated holes or insulated via connections through the metal core}
- 3/46 . Manufacturing multilayer circuits {(incorporating non-printed electric components in internal layers [H05K 1/185](#))}
- 3/4602 . . {characterized by a special circuit board as base or central core whereon additional circuit layers are built or additional circuit boards are laminated}
- 3/4605 . . . {made from inorganic insulating material}
- 3/4608 . . . {comprising an electrically conductive core}
- 3/4611 . . {by laminating two or more circuit boards ([H05K 3/4652](#) takes precedence)}
- 3/4614 . . . {the electrical connections between the circuit boards being made during lamination}
- 3/4617 {characterized by laminating only or mainly similar single-sided circuit boards}
- 3/462 {characterized by laminating only or mainly similar double-sided circuit boards}
- 3/4623 . . . {the circuit boards having internal via connections between two or more circuit layers before lamination, e.g. double-sided circuit boards ([H05K 3/462](#) takes precedence)}
- 3/4626 . . . {characterised by the insulating layers or materials ([H05K 3/4688](#) takes precedence)}
- 3/4629 {laminating inorganic sheets comprising printed circuits, e.g. green ceramic sheets}
- 3/4632 {laminating thermoplastic or uncured resin sheets comprising printed circuits without added adhesive materials between the sheets}
- 3/4635 {laminating flexible circuit boards using additional insulating adhesive materials between the boards}
- 3/4638 . . . {Aligning and fixing the circuit boards before lamination; Detecting or measuring the misalignment after lamination; Aligning external circuit patterns or via connections relative to internal circuits}
- 3/4641 . . . {having integrally laminated metal sheets or special power cores}
- 3/4644 . . {by building the multilayer layer by layer, i.e. build-up multilayer circuits (making via holes in the insulating layers [H05K 3/0011](#); special circuit boards as base or core whereon the multilayer is built [H05K 3/4602](#))}
- 3/4647 . . . {by applying an insulating layer around previously made via studs}
- 3/465 . . . {by applying an insulating layer having channels for the next circuit layer}
- 3/4652 . . . {Adding a circuit layer by laminating a metal foil or a preformed metal foil pattern ([H05K 3/4647](#) takes precedence)}
- 3/4655 {by using a laminate characterized by the insulating layer ([general-purpose insulating materials \[H05K 1/03\]\(#\), \[H05K 3/4673\]\(#\)](#))}
- 3/4658 {characterized by laminating a prefabricated metal foil pattern, e.g. by transfer}
- 3/4661 . . . {Adding a circuit layer by direct wet plating, e.g. electroless plating; insulating materials adapted therefor ([other insulating materials \[H05K 3/387\]\(#\)](#))}
- 3/4664 . . . {Adding a circuit layer by thick film methods, e.g. printing techniques or by other techniques for making conductive patterns by using pastes, inks or powders ([H05K 3/4647](#) takes precedence)}
- 3/4667 {characterized by using an inorganic intermediate insulating layer}
- 3/467 . . . {Adding a circuit layer by thin film methods ([H05K 3/4647](#) takes precedence)}
- 3/4673 . . . {Application methods or materials of intermediate insulating layers not specially adapted to any one of the previous methods of adding a circuit layer ([similar methods for protective coatings \[H05K 3/28\]\(#\)](#))}
- 3/4676 {Single layer compositions}
- 3/4679 . . . {Aligning added circuit layers or via connections relative to previous circuit layers}
- 3/4682 . . . {Manufacture of core-less build-up multilayer circuits on a temporary carrier or on a metal foil}
- 3/4685 . . {Manufacturing of cross-over conductors}
- 3/4688 . . {Composite multilayer circuits, i.e. comprising insulating layers having different properties (having a special base or central core [H05K 3/4602](#))}
- 3/4691 . . . {Rigid-flexible multilayer circuits comprising rigid and flexible layers, e.g. having in the bending regions only flexible layers}
- 3/4694 . . . {Partitioned multilayer circuits having adjacent regions with different properties, e.g. by adding or inserting locally circuit layers having a higher circuit density ([H05K 3/4691](#) takes precedence)}
- 3/4697 . . {having cavities, e.g. for mounting components ([H05K 3/4691](#) takes precedence)}
- 5/00 Casings, cabinets or drawers for electric apparatus (in general [A47B](#); radio receiver cabinets [H04B 1/08](#); television receiver cabinets [H04N 5/64](#); {constructional details or arrangements for computers [G06F 1/16](#)})**
- 5/0004 . {comprising several parts forming a closed casing}
- 5/0008 . . {assembled by screws}
- 5/0013 . . {assembled by resilient members}
- 5/0017 . {with display or control units}
- 5/0021 . {Side-by-side or stacked arrangements}
- 5/0026 . {provided with connectors and printed circuit boards [PCB], e.g. automotive electronic control units}
- 5/003 . . {having an integrally preformed housing}
- 5/0034 . . {having an overmolded housing covering the PCB}
- 5/0039 . . {having a tubular housing wherein the PCB is inserted longitudinally}

- 5/0043 . . {comprising a frame housing mating with two lids wherein the PCB is flat mounted on the frame housing}
- 5/0047 . . {having a two-part housing enclosing a PCB}
- 5/0052 . . . {characterized by joining features of the housing parts}
- 5/0056 . . . {characterized by features for protecting electronic components against vibration and moisture, e.g. potting, holders for relatively large capacitors}
- 5/006 . . . {characterized by features for holding the PCB within the housing}
- 5/0065 . . {wherein modules are associated together, e.g. electromechanical assemblies, modular structures}
- 5/0069 . . {having connector relating features for connecting the connector pins with the PCB or for mounting the connector body with the housing}
- 5/0073 . . {having specific features for mounting the housing on an external structure}
- 5/0078 . . {specially adapted for acceleration sensors, e.g. crash sensors, airbag sensors}
- 5/0082 . . {specially adapted for transmission control units, e.g. gearbox controllers}
- 5/0086 . {portable, e.g. battery operated apparatus (casings for switching devices [H01H 9/02](#))}
- 5/0091 . {Housing specially adapted for small components (for resistors [H01C](#); for capacitors [H01G](#); for integrated circuits [H01L 23/00](#))}
- 5/0095 . . {hermetically-sealed}
- 5/02 . Details
- 5/0204 . . {Mounting supporting structure on the outside of casings (mounting supporting structure in casings [H05K 7/14](#))}
- 5/0208 . . {Interlock mechanisms; Means for avoiding unauthorised use or function, e.g. tamperproof}
- 5/0213 . . {Thermal insulation; Venting means; Condensation eliminators}
- 5/0217 . . {Mechanical details of casings ([G06F 1/1613](#), [H01M 2/10](#), [H04M 1/0202](#) take precedence)}
- 5/0221 . . . {Locks; Latches}
- 5/0226 . . . {Hinges ([H02B 1/38](#) takes precedence)}
- 5/023 . . . {Handles; Grips}
- 5/0234 . . . {Feet; Stands; Pedestals, e.g. wheels for moving casing on floor}
- 5/0239 . . . {Lids; Hoods, e.g. members for covering aperture}
- 5/0243 . . . {for decorative purposes}
- 5/0247 . . {Electrical details of casings, e.g. terminals, passages for cables or wiring}
- 5/0252 . . {Labels, e.g. for identification, markings or configuration store}
- 5/0256 . . {of interchangeable modules or receptacles therefor, e.g. cartridge mechanisms}
- 5/026 . . . {having standardized interfaces (flash memory cards [G06K 19/077](#))}
- 5/0265 {of PCMCIA type}
- 5/0269 {Card housings therefor, e.g. covers, frames, PCB}
- 5/0273 {having extensions for peripherals, e.g. LAN, antennas (details of antennas [H01Q 1/2275](#))}
- 5/0278 {of USB type (details relating to connectors [H01R 27/00](#))}
- 5/0282 . . . {Adapters for connecting cards having a first standard in receptacles having a second standard}
- 5/0286 . . . {Receptacles therefor, e.g. card slots, module sockets, card groundings}
- 5/0291 {for multiple cards}
- 5/0295 {having ejection mechanisms}
- 5/03 . . Covers
- 5/04 . Metal casings
- 5/06 . Hermetically-sealed casings ((specially adapted for small components [H05K 5/0095](#))}
- 5/061 . . {sealed by a gasket held between a removable cover and a body, e.g. O-ring, packing}
- 5/062 . . {sealed by a material injected between a non-removable cover and a body, e.g. hardening in situ}
- 5/063 . . {sealed by a labyrinth structure provided at the joining parts}
- 5/064 . . {sealed by potting, e.g. waterproof resin poured in a rigid casing}
- 5/065 . . {sealed by encapsulation, e.g. waterproof resin forming an integral casing, injection moulding}
- 5/066 . . {sealed by fusion of the joining parts without bringing material; sealed by brazing}
- 5/067 . . {containing a dielectric fluid}
- 5/068 . . {having a pressure compensation device, e.g. membrane ([venting means H05K 5/0213](#))}
- 5/069 . . {Other details of the casing, e.g. wall structure, passage for a connector, a cable, a shaft}
- 7/00 Constructional details common to different types of electric apparatus (casings, cabinets, drawers [H05K 5/00](#))**
- 7/005 . {arrangements of circuit components without supporting structure}
- 7/02 . Arrangements of circuit components or wiring on supporting structure
- 7/023 . . {Stackable modules}
- 7/026 . . {Multiple connections subassemblies}
- 7/04 . . on conductive chassis
- 7/06 . . on insulating boards {, e.g. wiring harnesses (for printed circuits [H05K 1/18](#), [H05K 3/30](#))}
- 7/08 . . . on perforated boards
- 7/10 . . Plug-in assemblages of components, {e.g. IC sockets (for connection on printed circuit board [H01R 23/6806](#))}
- 7/1007 . . . {with means for increasing contact pressure at the end of engagement of coupling parts}
- 7/1015 . . . {having exterior leads}
- 7/1023 {co-operating by abutting, e.g. flat pack}
- 7/103 {co-operating by sliding, e.g. DIP carriers}
- 7/1038 {with spring contact pieces ([H05K 7/1046](#) takes precedence)}
- 7/1046 {J-shaped leads}
- 7/1053 . . . {having interior leads}
- 7/1061 {co-operating by abutting}
- 7/1069 {with spring contact pieces}
- 7/1076 {co-operating by sliding}
- 7/1084 {pin grid array package carriers}
- 7/1092 . . . {with built-in components, e.g. intelligent sockets}
- 7/12 . . Resilient or clamping means for holding component to structure ([holding two-part couplings together H01R 13/00](#))

- 7/14 . . . Mounting supporting structure in casing or on frame or rack { [\(H05K 7/18 takes precedence; test adapters G01R 31/2808\)](#) }
- 7/1401 . . . { comprising clamping or extracting means [\(H05K 7/10 takes precedence\)](#) }
- 7/1402 . . . { for securing or extracting printed circuit boards }
 - 7/1404 { by edge clamping, e.g. wedges }
 - 7/1405 { by clips or resilient members, e.g. hooks }
 - 7/1407 { by turn-bolt or screw member }
 - 7/1408 { by a unique member which latches several boards, e.g. locking bars }
 - 7/1409 { by lever-type mechanisms }
- 7/1411 . . . { for securing or extracting box-type drawers }
- 7/1412 { hold down mechanisms, e.g. avionic racks }
- 7/1414 . . . { with power interlock }
- 7/1415 . . . { manual gripping tools }
- 7/1417 . . { having securing means for mounting boards, plates or wiring boards [\(H05K 7/1461 takes precedence\)](#) }
- 7/1418 . . . { Card guides, e.g. grooves [\(H05K 7/1425 takes precedence\)](#) }
- 7/142 . . . { Spacers not being card guides }
- 7/1421 . . { Drawers for printed circuit boards }
- 7/1422 . . { Printed circuit boards receptacles, e.g. stacked structures, electronic circuit modules or box like frames }
- 7/1424 . . . { Card cages }
- 7/1425 { of standardised dimensions, e.g. 19"-subrack }
- 7/1427 . . . { Housings }
- 7/1428 { for small modular apparatus with terminal block }
- 7/1429 { for circuits carrying a CPU and adapted to receive expansion cards }
- 7/1431 { Retention mechanisms for CPU modules }
- 7/1432 { for power drive units }
- 7/1434 { for electronics exposed to high gravitational force; Cylindrical housings }
- 7/1435 . . . { Expandable constructions }
- 7/1438 . . { Back panels or connecting means therefor; Terminals; Coding means to avoid wrong insertion }
- 7/1439 . . . { Back panel mother boards }
- 7/1441 { with a segmented structure }
- 7/1442 { with a radial structure }
- 7/1444 { Complex or three-dimensional-arrangements; Stepped or dual mother boards }
- 7/1445 { with double-sided connections }
- 7/1447 . . . { External wirings; Wiring ducts; Laying cables }
- 7/1448 { with connections to the front board }
- 7/1449 { with connections to the back board }
- 7/1451 { with connections between circuit boards or units }
- 7/1452 . . . { Mounting of connectors; Switching; Reinforcing of back panels }
- 7/1454 { Alignment mechanisms; Drawout cases }
- 7/1455 { Coding for prevention of wrong insertion }
- 7/1457 . . . { Power distribution arrangements }
- 7/1458 . . . { Active back panels; Back panels with filtering means }
- 7/1459 { Circuit configuration, e.g. routing signals }
- 7/1461 . . . { Slidable card holders; Card stiffeners; Control or display means therefor }
- 7/1462 . . . { for programmable logic controllers [PLC] for automation and/or industrial process control [\(programmable logic controllers per se G05B 19/05\)](#) }
- 7/1464 { Functional units accommodated in the same PLC module housing }
- 7/1465 { Modular PLC assemblies with separable functional units }
- 7/1467 { PLC mounted in a cabinet or chassis }
- 7/1468 { Mechanical features of input/output (I/O) modules }
- 7/1469 { Terminal blocks for connecting sensors [\(terminal blocks in general H01R 9/24\)](#) }
- 7/1471 { Modules for controlling actuators }
- 7/1472 { Bus coupling modules, e.g. bus distribution modules }
- 7/1474 { Mounting of modules, e.g. on a base or rail or wall }
- 7/1475 { Bus assemblies for establishing communication between PLC modules }
- 7/1477 { including backplanes }
- 7/1478 { including a segmented bus }
- 7/1479 { including decentralized modules, e.g. connected to other modules using fieldbus }
- 7/1481 { User interface, e.g. status displays; Programming interface, e.g. connector for computer programming; Monitoring }
- 7/1482 { PLC power supply; PLC accessories, e.g. for safety }
- 7/1484 { Electrical diagrams relating to constructional features, e.g. signal routing within PLC; Provisions for disaster recovery, e.g. redundant systems }
- 7/1485 . . . { Servers; Data center rooms, e.g. 19-inch computer racks }
- 7/1487 { Blade assembly, e.g. cases and inner arrangements }
- 7/1488 { Cabinets therefore, e.g. chassis, racks }
- 7/1489 { characterized by the mounting of blades therein, e.g. brackets, rails, trays [\(H05K 7/1491 takes precedence\)](#) }
- 7/1491 { having cable management arrangements [\(management of optical cables G02B 6/444; in telecommunication cabinets H04Q 1/06\)](#) }
- 7/1492 { having electrical distribution arrangements, e.g. power supply or data communications }
- 7/1494 { having hardware for monitoring blades, e.g. keyboards, displays [\(methods or software therefore H05K 7/1498\)](#) }
- 7/1495 { providing data protection in case of earthquakes, floods, storms, nuclear explosions, intrusions, fire }
- 7/1497 { Rooms for data centers; Shipping containers therefor }
- 7/1498 { Resource management, Optimisation arrangements, e.g. configuration, identification, tracking, physical location [\(thermal management H05K 7/20836\)](#) }
- 7/16 . . . on hinges or pivots
- 7/18 . . . Construction of rack or frame
- 7/183 . . . { support rails therefor }

- 7/186 . . {for supporting telecommunication equipment
(selecting apparatus [H04Q 1/02](#))}
- 7/20 . Modifications to facilitate cooling, ventilating,
or heating {(of printed circuits [H05K 1/0201](#);
of resistors [H01C](#); of capacitors [H01G](#); of
individual semiconductor components [H01L 23/34](#),
[H01L 31/024](#); of LEDs [H01L 33/64](#); of personal
computers [G06F 1/20](#))}
- 7/20009 . . {using a gaseous coolant in electronic enclosures
(in cabinets of standardized dimensions
[H05K 7/20536](#); in server cabinets [H05K 7/20709](#);
in vehicle electronic casings [H05K 7/20845](#);
in power control electronics [H05K 7/2089](#); in
displays [H05K 7/20954](#))}
- 7/20127 . . . {Natural convection}
- 7/20136 . . . {Forced ventilation, e.g. by fans ([H05K 7/202](#)
takes precedence)}
- 7/20145 {Means for directing air flow, e.g. ducts,
deflectors, plenum or guides}
- 7/20154 {Heat dissipaters coupled to components}
- 7/20163 {the components being isolated from air
flow, e.g. hollow heat sinks, wind tunnels
or funnels}
- 7/20172 {Fan mounting or fan specifications (blowers
in general [F04D 29/601](#))}
- 7/20181 {Filters; Louvers (filters in general
[B01D 46/00](#))}
- 7/2019 {Fan safe systems, e.g. mechanical devices
for non stop cooling}
- 7/202 . . . {Air circulating in closed loop within enclosure
wherein heat is removed through heat-
exchangers}
- 7/20209 . . . {Thermal management, e.g. fan control}
- 7/20218 . . {using a liquid coolant without phase change in
electronic enclosures (in cabinets of standardized
dimensions [H05K 7/20536](#); in server cabinets
[H05K 7/20709](#); in vehicle electronic casings
[H05K 7/20845](#); in power control electronics
[H05K 7/2089](#); in displays [H05K 7/20954](#))}
- 7/20236 . . . {by immersion}
- 7/20245 . . . {by natural convection; Thermosiphons}
- 7/20254 . . . {Cold plates transferring heat from heat source
to coolant}
- 7/20263 . . . {Heat dissipaters releasing heat from coolant}
- 7/20272 . . . {Accessories for moving fluid, for expanding
fluid, for connecting fluid conduits, for
distributing fluid, for removing gas or for
preventing leakage, e.g. pumps, tanks or
manifolds}
- 7/20281 . . . {Thermal management, e.g. liquid flow
control}
- 7/2029 . . {using a liquid coolant with phase change in
electronic enclosures (in cabinets of standardized
dimensions [H05K 7/20536](#); in server cabinets
[H05K 7/20709](#); in vehicle electronic casings
[H05K 7/20845](#); in power control electronics
[H05K 7/2089](#); in displays [H05K 7/20954](#))}
- 7/203 . . . {by immersion}
- 7/20309 . . . {Evaporators}
- 7/20318 . . . {Condensers}
- 7/20327 . . . {Accessories for moving fluid, for connecting
fluid conduits, for distributing fluid or for
preventing leakage, e.g. pumps, tanks or
manifolds}
- 7/20336 . . . {Heat pipes, e.g. wicks or capillary pumps}
- 7/20345 . . . {Sprayers; Atomizers}
- 7/20354 . . . {Refrigerating circuit comprising a
compressor}
- 7/20363 . . . {Refrigerating circuit comprising a sorber}
- 7/20372 . . . {Cryogenic cooling; Nitrogen liquid cooling}
- 7/20381 . . . {Thermal management, e.g. evaporation
control}
- 7/2039 . . {characterised by the heat transfer by conduction
from the heat generating element to a dissipating
body (arrangements for increasing/decreasing
heat-transfer, e.g. fins details, [F28F 13/00](#))}
- 7/20409 . . . {Outer radiating structures on heat dissipating
housings, e.g. fins integrated with the housing}
- 7/20418 {the radiating structures being additional and
fastened onto the housing}
- 7/20427 {having radiation enhancing surface
treatment, e.g. black coating}
- 7/20436 . . . {Inner thermal coupling elements in heat
dissipating housings, e.g. protrusions or
depressions integrally formed in the housing}
- 7/20445 {the coupling element being an additional
piece, e.g. thermal standoff}
- 7/20454 {with a conformable or flexible structure
compensating for irregularities, e.g.
cushion bags, thermal paste}
- 7/20463 {Filling compound, e.g. potted resin}
- 7/20472 {Sheet interfaces}
- 7/20481 {characterised by the material
composition exhibiting specific thermal
properties}
- 7/2049 {Pressing means used to urge contact, e.g.
springs}
- 7/205 . . . {Thermal paths through the printed circuit
board [PCB] (details of PCBs related to heat
transfer [H05K 1/0201](#))}
- 7/20509 . . . {Cold plates, e.g. multi-component heat
spreader, support plates, non closed structures}
- 7/20518 . . . {Unevenly distributed heat load, e.g. different
sectors at different temperatures, localised
cooling, hot spots}
- 7/20536 . . {for racks or cabinets of standardized dimensions,
e.g. 19-inch electronic racks}
- 7/20545 . . . {Natural convection of gaseous coolant; Heat
transfer by conduction from electronic boards}
- 7/20554 . . . {Forced ventilation of a gaseous coolant (in
closed loop [H05K 7/206](#) or [H05K 7/20609](#) or
[H05K 7/20618](#))}
- 7/20563 {within sub-racks for removing heat from
electronic boards}
- 7/20572 {within cabinets for removing heat from sub-
racks, e.g. plenum}
- 7/20581 {Cabinets including a drawer for fans}
- 7/2059 {within rooms for removing heat from
cabinets, e.g. by air conditioning device}
- 7/206 . . . {Air circulating in closed loop within cabinets
wherein heat is removed through air-to-air
heat-exchanger}
- 7/20609 . . . {Air circulating in closed loop within cabinets
wherein heat is removed through air-to-liquid
heat-exchanger}
- 7/20618 . . . {Air circulating in different modes under
control of air guidance flaps}
- 7/20627 . . . {Liquid coolant without phase change}

- 7/20636 . . . {within sub-racks for removing heat from electronic boards}
- 7/20645 . . . {within cabinets for removing heat from sub-racks}
- 7/20654 . . . {within rooms for removing heat from cabinets}
- 7/20663 . . . {Liquid coolant with phase change, e.g. heat pipes}
- 7/20672 . . . {within sub-racks for removing heat from electronic boards}
- 7/20681 . . . {within cabinets for removing heat from sub-racks}
- 7/2069 . . . {within rooms for removing heat from cabinets}
- 7/207 . . . {Thermal management, e.g. cabinet temperature control}
- 7/20709 . . {for server racks or cabinets; for data centers, e.g. 19-inch computer racks}
- 7/20718 . . . {Forced ventilation of a gaseous coolant (in closed loop [H05K 7/20754](#))}
- 7/20727 . . . {within server blades for removing heat from heat source}
- 7/20736 . . . {within cabinets for removing heat from server blades}
- 7/20745 . . . {within rooms for removing heat from cabinets, e.g. by air conditioning device}
- 7/20754 . . . {Air circulating in closed loop within cabinets}
- 7/20763 . . . {Liquid cooling without phase change}
- 7/20772 . . . {within server blades for removing heat from heat source}
- 7/20781 . . . {within cabinets for removing heat from server blades}
- 7/2079 . . . {within rooms for removing heat from cabinets}
- 7/208 . . . {Liquid cooling with phase change}
- 7/20809 . . . {within server blades for removing heat from heat source}
- 7/20818 . . . {within cabinets for removing heat from server blades}
- 7/20827 . . . {within rooms for removing heat from cabinets, e.g. air conditioning devices}
- 7/20836 . . . {Thermal management, e.g. server temperature control}
- 7/20845 . . {for vehicle electronic casings}
- 7/20854 . . . {Heat transfer by conduction from internal heat source to heat radiating structure ([H05K 7/20863](#) takes precedence)}
- 7/20863 . . . {Forced ventilation, e.g. on heat dissipaters coupled to components}
- 7/20872 . . . {Liquid coolant without phase change}
- 7/20881 . . . {Liquid coolant with phase change}
- 7/2089 . . {for power electronics, e.g. for inverters for controlling motor}
- 7/209 . . . {Heat transfer by conduction from internal heat source to heat radiating structure ([H05K 7/20909](#) takes precedence)}
- 7/20909 . . . {Forced ventilation, e.g. on heat dissipaters coupled to components}
- 7/20918 . . . {the components being isolated from air flow, e.g. hollow heat sinks, wind tunnels or funnels}
- 7/20927 . . . {Liquid coolant without phase change}
- 7/20936 . . . {Liquid coolant with phase change}
- 7/20945 . . . {Thermal management, e.g. inverter temperature control}
- 7/20954 . . {for display panels (cooling means for computer displays [G06F 1/20](#); heating or cooling of liquid crystal cells [G02F 1/133382](#); cooling for projectors [G03B 21/16](#); plasma display panels [per se](#) [H01J 17/49](#))}
- 7/20963 . . . {Heat transfer by conduction from internal heat source to heat radiating structure ([H05K 7/20972](#) takes precedence)}
- 7/20972 . . . {Forced ventilation, e.g. on heat dissipaters coupled to components}
- 7/20981 . . . {Liquid coolant without phase change}
- 7/2099 . . . {Liquid coolant with phase change}
- 9/00 Screening of apparatus or components against electric or magnetic fields** (devices for absorbing radiation from an aerial [H01Q 17/00](#); {screening of semiconductor devices [H01L 24/00](#), [H01L 23/58](#); screening structurally associated with dynamo-electric machines [H02K 11/00](#); shielding against nuclear radiation [G21F](#)})
- 9/0001 . {Rooms, chambers (building construction in general [E04B](#); anechoic room [G01R 29/0821](#); Nuclear magnetic resonance [G01R 33/42](#))}
- 9/0003 . . {Shielded walls, floors, ceilings, e.g. wallpaper, wall panel, electro-conductive plaster, concrete, cement, mortar}
- 9/0005 . . {Shielded windows (window for building construction in general [E06B 5/00](#))}
- 9/0007 . {Casings (standardised racks [H05K 9/0062](#))}
- 9/0009 . . {with provisions to reduce EMI leakage through the joining parts}
- 9/0015 . . {Gaskets or seals}
- 9/0016 . . . {having a spring contact}
- 9/0018 . . {with provisions to reduce aperture leakages in walls, e.g. terminals, connectors, cables}
- 9/002 . . {with localised screening}
- 9/0022 . . . {of components mounted on printed circuit boards [PCB] (shields integrated within component packages [H01L 23/552](#); shields integrated within PCB [H05K 1/0218](#))}
- 9/0024 . . . {Shield cases mounted on a PCB, e.g. cans, caps, conformal shields}
- 9/0026 {integrally formed from metal sheet}
- 9/0028 {with retainers or specific soldering features}
- 9/003 {made from electro-conductive plastic material or combining different shielding materials}
- 9/0032 {having multiple parts, e.g. frames mating with lids}
- 9/0033 {disposed on both PCB faces}
- 9/0035 {with retainers mounted beforehand on the PCB, e.g. clips}
- 9/0037 {Housings with compartments containing a PCB, e.g. partitioning walls}
- 9/0039 . . . {Ground layout on printed circuit board}
- 9/0041 . . {Ventilation panels having provisions for screening}
- 9/0043 . . {being flexible containers, e.g. pouch, pocket, bag}
- 9/0045 . . {being rigid plastic containers having a coating of shielding material}

9/0047	. . {being rigid plastic containers having conductive particles, fibres or mesh embdded therein}	10/00	Arrangements for improving the operating reliability of electronic equipment, e.g. by providing a similar standby unit
9/0049	. . {being metallic containers}	11/00	Combination of a radio or television receiver with apparatus having a different main function
9/005	. . {being nesting containers}		{(combined with clocks G04B 47/00 ; controlled by a clock G04C 21/28)}
9/0052	. . {Shielding other than Faraday cages}	11/02	. with vehicles
9/0054	. . {specially adapted for display applications}	13/00	Apparatus or processes specially adapted for manufacturing or adjusting assemblages of electric components
9/0056	. . {specially adapted for microwave applications}		
9/0058	. . {specially adapted for optoelectronic applications}	13/0007	. {using handtools (for mounting on a circuit board H05K 13/0447)}
9/006	. . {specially adapted for signal processing applications, e.g. CATV, tuner, antennas amplifier}	13/0015	. {Orientation; Alignment; Positioning}
9/0062	. {Structures of standardised dimensions, e.g. 19" rack, chassis for servers or telecommunications}	13/0023	. {Making assemblies of electric components, e.g. modules (H05K 13/04 take precedence)}
9/0064	. {Earth or grounding circuit}	13/003	. {Placing of components on belts holding the terminals}
9/0066	. {Constructional details of transient suppressor (protective circuit H02H)}	13/0038	. . {placing the components in a predetermined order}
9/0067	. {Devices for protecting against damage from electrostatic discharge (materials see H05K 9/0079)}	13/0046	. {Encapsulation of electrical assemblies in resins (hermetically-sealed casings H05K 5/06)}
9/0069	. {Methods for measuring the shielding efficiency; Apparatus therefor; Isolation container for testing}	13/0053	. {Means for helping with the manual mounting of components, e.g. special tables, light spots indicating the place for mounting (handtools H05K 13/0447)}
9/0071	. {Active shielding}	13/0061	. {Tools for holding the circuit boards during processing; handling transport of printed circuit boards}
9/0073	. {Shielding materials (H05K 9/0003 takes precedence)}	13/0069	. . {Holders for printed circuit boards}
9/0075	. . {Magnetic shielding materials (magnetic material in general H01F 1/00 ; for electrical motor H02K 11/00 ; for transformer H01F 27/28)}	13/0076	. . {Straightening or aligning terminal leads of pins mounted on boards, during transport of the boards (during the mounting operation, after fitting components on the board H05K 13/0473)}
9/0077	. . . {comprising superconductors (superconductors in general H01L 39/00)}	13/0084	. {Containers and magazines for components, e.g. tube-like magazines}
9/0079	. . {Electrostatic discharge protection, e.g. ESD treated surface for rapid dissipation of charges}	13/0092	. {Treatment of the terminal leads as a separate operation (during transport H05K 13/0076 , H05K 13/023 ; during mounting H05K 13/04)}
9/0081	. . {Electromagnetic shielding materials, e.g. EMI, RFI shielding (H05K 9/0003 takes precedence)}	13/02	. Feeding of components (in general B65G)
9/0083	. . . {comprising electro-conductive non-fibrous particles embedded in an electrically insulating supporting structure, e.g. powder, flakes, whiskers (H05K 9/0086 takes precedence)}	13/021	. . {Loading or unloading of containers (H05K 13/028 takes precedence)}
9/0084	. . . {comprising a single continuous metallic layer on an electrically insulating supporting structure, e.g. metal foil, film, plating coating, electro-deposition, vapour-deposition}	13/022	. . {with orientation of the elements (orientation while mounting H05K 13/0413 ; in general B23P 19/00)}
9/0086	. . . {comprising a single discontinuous metallic layer on an electrically insulating supporting structure, e.g. metal grid, perforated metal foil, film, aggregated flakes, sintering}	13/023	. . {with bending or straightening of the terminal leads (bending and cutting after the mounting on a p.c. board H05K 13/0473)}
9/0088	. . . {comprising a plurality of shielding layers; combining different shielding material structure}	13/024	. . . {Straightening or aligning terminal leads}
9/009	. . . {comprising electro-conductive fibres, e.g. metal fibres, carbon fibres metallised textile fibres, electro-conductive mesh, woven, non-woven mat, fleece, cross-linked (Screening during electrotherapy A61N 1/16)}	13/025 {of components having oppositely extending terminal leads}
9/0092	. . . {comprising electro-conductive pigments, e.g. paint, ink, tampon printing}	13/026 {of components having terminal leads in side by side relationship, e.g. using combing elements}
9/0094	. . {being light-transmitting, e.g. transparent, translucent}	13/027	. . {Fluid transport of components}
9/0096	. . . {for television displays, e.g. plasma display panel}	13/028	. . {Simultaneously loading a plurality of loose objects, e.g. by means of vibrations, pressure differences, magnetic fields}
9/0098	. . {for shielding electrical cables}	13/029	. . {Feeding axial lead components, e.g. using vibrating bowls, magnetic fields (H05K 13/022 takes precedence)}
		13/04	. Mounting of components {, e.g. of leadless components}

13/0404	. . {pick and place heads or apparatus, e.g. with jaws}	2201/0145	. . . Polyester, e.g. polyethylene terephthalate [PET], polyethylene naphthalate [PEN]
13/0408	. . . {incorporating a sucking device (H05K 13/0413 takes precedence)}	2201/015	. . . Fluoropolymer, e.g. polytetrafluoroethylene [PTFE]
13/0413	. . . {with orientation of the component while holding it (orientation while feeding H05K 13/022)}	2201/0154	. . . Polyimide
13/0417	. . {Feeding with belts}	2201/0158	. . . Polyalkene or polyolefin, e.g. polyethylene [PE], polypropylene [PP]
13/0421	. . . {with treatment of the terminal leads (bending and cutting after fitting on a circuit board H05K 13/0473)}	2201/0162	. . . Silicon containing polymer, e.g. silicone
13/0426	. . . {for components being oppositely extending terminal leads (H05K 13/0421 takes precedence)}	2201/0166	. . . Polymeric layer used for special processing, e.g. resist for etching insulating material or photoresist used as a mask during plasma etching
13/043	. . {Feeding one by one by other means than belts}	2201/017	. . . Glass ceramic coating, e.g. formed on inorganic substrate (inorganic, non-metallic substrates H05K 1/0306)
13/0434	. . . {with containers}	2201/0175	. . . Inorganic, non-metallic layer, e.g. resist or dielectric for printed capacitor
13/0439	. . . {incorporating means for treating the terminal leads only before insertion}	2201/0179	. . . Thin film deposited insulating layer, e.g. inorganic layer for printed capacitor
13/0443	. . . {incorporating means for treating the terminal leads before and after insertion or only after insertion}	2201/0183	. . Dielectric layers
13/0447	. . {Hand tools therefor}	2201/0187	. . . with regions of different dielectrics in the same layer, e.g. in a printed capacitor for locally changing the dielectric properties
13/0452	. . {different components being guided to the same mounting place}	2201/0191	. . . wherein the thickness of the dielectric plays an important role
13/0456	. . {simultaneously punching the circuit board}	2201/0195	. . . Dielectric or adhesive layers comprising a plurality of layers, e.g. in a multilayer structure
13/046	. . {Surface mounting (surface mounted components H05K 3/341)}	2201/02	. Fillers; Particles; Fibers; Reinforcement materials
13/0465	. . . {by soldering (H05K 13/0469 takes precedence; soldering apparatus in general B23K)}	2201/0203	. . Fillers and particles
13/0469	. . . {by applying a glue or viscous material}	2201/0206	. . . Materials
13/0473	. . {Cutting and clinching the terminal ends of the leads after they are fitted on a circuit board (during transport H05K 13/0076)}	2201/0209 Inorganic, non-metallic particles
13/0478	. . {Simultaneously mounting of different components}	2201/0212 Resin particles
13/0482	. . . {using templates; using magazines, the configuration of which corresponds to the sites on the boards where the components have to be attached}	2201/0215 Metallic fillers
13/0486	. . {Replacement and removal of components}	2201/0218 Composite particles, i.e. first metal coated with second metal
13/0491	. . . {Hand tools therefor}	2201/0221 Insulating particles having an electrically conductive coating
13/0495	. . {having a plurality of work-stations}	2201/0224 Conductive particles having an insulating coating
13/06	. Wiring by machine	2201/0227 Insulating particles having an insulating coating
13/065	. . {Accessories therefor, e.g. light spots}	2201/023 Hard particles, i.e. particles in conductive adhesive at least partly penetrating an electrode
13/08	. Monitoring manufacture of assemblages	2201/0233 Deformable particles (insulating particles having an electrically conductive coating H05K 2201/0221)
2201/00	Indexing scheme relating to printed circuits covered by H05K 1/00	2201/0236 Plating catalyst as filler in insulating material (catalytic ink H05K 2203/0709)
2201/01	. Dielectrics	2201/0239 Coupling agent for particles (using a coupling agent to improve the adhesion between an insulating substrate and a metal H05K 3/389)
2201/0104	. . Properties and characteristics in general	2201/0242	. . . Shape of an individual particle
2201/0108	. . . Transparent	2201/0245 Flakes, flat particles or lamellar particles
2201/0112	. . . Absorbing light, e.g. dielectric layer with carbon filler for laser processing	2201/0248 Needles or elongated particles; Elongated cluster of chemically bonded particles (microfibers H05K 2201/0251 ; stacked conductors H05K 2201/0379)
2201/0116	. . . Porous, e.g. foam	2201/0251 Non-conductive microfibers (relatively short elongated particles H05K 2201/0248)
2201/012	. . . Flame-retardant; Preventing of inflammation	2201/0254 Microballoons or hollow filler particles
2201/0125	. . . Shrinkable, e.g. heat-shrinkable polymer	2201/0257 Nanoparticles (inks comprising nanoparticles H05K 1/097)
2201/0129	. . . Thermoplastic polymer, e.g. auto-adhesive layer; Shaping of thermoplastic polymer		
2201/0133	. . . Elastomeric or compliant polymer (elastomeric conductor H05K 2201/0314)		
2201/0137	. . Materials		
2201/0141	. . . Liquid crystal polymer [LCP]		

- 2201/026 Nanotubes or nanowires
- 2201/0263 . . . Details about a collection of particles
- 2201/0266 Size distribution
- 2201/0269 Non-uniform distribution or concentration of particles
- 2201/0272 Mixed conductive particles, i.e. using different conductive particles, e.g. differing in shape
- 2201/0275 . . Fibers and reinforcement materials
- 2201/0278 . . . Polymeric fibers
- 2201/0281 . . . Conductive fibers
- 2201/0284 . . . Paper, e.g. as reinforcement ([paper sheet substrates H05K 1/0386](#))
- 2201/0287 . . . Unidirectional or parallel fibers
- 2201/029 . . . Woven fibrous reinforcement or textile ([textile substrates H05K 1/038](#))
- 2201/0293 . . . Non-woven fibrous reinforcement
- 2201/0296 . . . Fibers with a special cross-section, e.g. elliptical
- 2201/03 . . Conductive materials
- 2201/0302 . . Properties and characteristics in general
- 2201/0305 . . . Solder used for other purposes than connections between PCB or components, e.g. for filling vias or for programmable patterns
- 2201/0308 . . . Shape memory alloy [SMA]
- 2201/0311 . . . Metallic part with specific elastic properties, e.g. bent piece of metal as electrical contact
- 2201/0314 . . . Elastomeric connector or conductor, e.g. rubber with metallic filler ([elastomeric dielectric H05K 2201/0133](#))
- 2201/0317 . . . Thin film conductor layer; Thin film passive component
- 2201/032 . . Materials
- 2201/0323 . . . Carbon
- 2201/0326 . . . Inorganic, non-metallic conductor, e.g. indium-tin oxide [ITO]
- 2201/0329 . . . Intrinsically conductive polymer [ICP]; Semiconductive polymer
- 2201/0332 . . Structure of the conductor
- 2201/0335 . . . Layered conductors or foils
- 2201/0338 Layered conductor, e.g. layered metal substrate, layered finish layer, layered thin film adhesion layer ([etched tri-metal structure H05K 2201/0361](#))
- 2201/0341 Intermediate metal, e.g. before reinforcing of conductors by plating
- 2201/0344 Electroless sublayer, e.g. Ni, Co, Cd or Ag; Transferred electroless sublayer
- 2201/0347 Overplating, e.g. for reinforcing conductors or bumps; Plating over filled vias ([reinforcing the conductive pattern H05K 3/24](#))
- 2201/035 Paste overlayer, i.e. conductive paste or solder paste over conductive layer
- 2201/0352 Differences between the conductors of different layers of a multilayer
- 2201/0355 Metal foils
- 2201/0358 Resin coated copper [RCC]
- 2201/0361 Etched tri-metal structure, i.e. metal layers or metal patterns on both sides of a different central metal layer which is later at least partly etched
- 2201/0364 . . . Conductor shape
- 2201/0367 Metallic bump or raised conductor not used as solder bump ([solder materials or compositions and methods of application thereof H05K 3/3457](#))
- 2201/037 Hollow conductors, i.e. conductors partially or completely surrounding a void, e.g. hollow waveguides
- 2201/0373 Conductors having a fine structure, e.g. providing a plurality of contact points with a structured tool ([providing micro- or nanometer scale roughness on a metal surface H05K 2203/0307](#))
- 2201/0376 Flush conductors, i.e. flush with the surface of the printed circuit
- 2201/0379 Stacked conductors
- 2201/0382 Continuously deformed conductors
- 2201/0385 Displaced conductors
- 2201/0388 . . . Other aspects of conductors
- 2201/0391 Using different types of conductors
- 2201/0394 Conductor crossing over a hole in the substrate
- 2201/0397 Tab ([forming integral conductive tabs H05K 3/4092](#))
- 2201/04 . . Assemblies of printed circuits
- 2201/041 . . Stacked PCBs, i.e. having neither an empty space nor mounted components in between
- 2201/042 . . Stacked spaced PCBs; Planar parts of folded flexible circuits having mounted components in between or spaced from each other
- 2201/043 . . Stacked PCBs with their backs attached to each other without electrical connection
- 2201/044 . . Details of backplane or midplane for mounting orthogonal PCBs
- 2201/045 . . Hierarchy auxiliary PCB, i.e. more than two levels of hierarchy for daughter PCBs are important
- 2201/046 . . Planar parts of folded PCBs making an angle relative to each other ([assembling printed circuits perpendicularly to each other H05K 3/366](#))
- 2201/047 . . Box-like arrangements of PCBs
- 2201/048 . . Second PCB mounted on first PCB by inserting in window or holes of the first PCB
- 2201/049 . . PCB for one component, e.g. for mounting onto mother PCB
- 2201/05 . . Flexible printed circuits [FPCs]
- 2201/051 . . Rolled
- 2201/052 . . Branched
- 2201/053 . . Tails
- 2201/055 . . Folded back on itself
- 2201/056 . . Folded around rigid support or component
- 2201/057 . . Shape retainable
- 2201/058 . . Direct connection between two or more FPCs or between flexible parts of rigid PCBs
- 2201/06 . . Thermal details
- 2201/062 . . Means for thermal insulation, e.g. for protection of parts
- 2201/064 . . Fluid cooling, e.g. by integral pipes
- 2201/066 . . Heatsink mounted on the surface of the PCB ([heatsink inserted in the PCB H05K 2201/10416](#))
- 2201/068 . . wherein the coefficient of thermal expansion is important
- 2201/07 . . Electric details
- 2201/0707 . . Shielding
- 2201/0715 . . . provided by an outer layer of PCB

2201/0723	. . .	provided by an inner layer of PCB	2201/09227	Layout details of a plurality of traces, e.g. escape layout for Ball Grid Array [BGA] mounting
2201/073	. .	High voltage adaptations (overvoltage protection H05K 1/0257)	2201/09236	Parallel layout (layout of balanced signal pairs H05K 1/0245 ; superposed layout H05K 2201/09672)
2201/0738	. . .	Use of voltage responsive materials, e.g. voltage switchable dielectric or varistor materials	2201/09245	Crossing layout (alternating conductors H05K 2201/097)
2201/0746	. . .	Protection against transients, e.g. layout adapted for plugging of connector	2201/09254	Branched layout
2201/0753	. .	Insulation	2201/09263	Meander
2201/0761	. . .	Insulation resistance, e.g. of the surface of the PCB between the conductors	2201/09272	Layout details of angles or corners
2201/0769	. . .	Anti metal-migration, e.g. avoiding tin whisker growth	2201/09281	Layout details of a single conductor (meander H05K 2201/09263 ; layout details of angles or corners H05K 2201/09272)
2201/0776	. .	Resistance and impedance	2201/0929	. . .	Conductive planes
2201/0784	. . .	Uniform resistance, i.e. equalizing the resistance of a number of conductors	2201/093	Layout of power planes, ground planes or power supply conductors, e.g. having special clearance holes therein (reduction of cross-talk, noise or interference by patterned shielding planes, ground planes or power planes H05K 1/0224)
2201/0792	. . .	Means against parasitic impedance; Means against eddy currents	2201/09309	Core having two or more power planes; Capacitive laminate of two power planes
2201/08	. .	Magnetic details	2201/09318	Core having one signal plane and one power plane
2201/083	. .	Magnetic materials	2201/09327	Special sequence of power, ground and signal layers in multilayer PCB
2201/086	. . .	for inductive purposes, e.g. printed inductor with ferrite core	2201/09336	Signal conductors in same plane as power plane
2201/09	. .	Shape and layout	2201/09345	Power and ground in the same plane; Power planes for two voltages in one plane
2201/09009	. .	Substrate related	2201/09354	Ground conductor along edge of main surface (edge contacts H05K 3/403)
2201/09018	. . .	Rigid curved substrate	2201/09363	wherein only contours around conductors are removed for insulation
2201/09027	. . .	Non-rectangular flat PCB, e.g. circular	2201/09372	. . .	Pads and lands
2201/09036	. . .	Recesses or grooves in insulating substrate (recess in metallic substrate H05K 2201/09745)	2201/09381	Shape of non-curved single flat metallic pad, land or exposed part thereof; Shape of electrode of leadless component (notches in edge pads H05K 2201/09181)
2201/09045	. . .	Locally raised area or protrusion of insulating substrate (rigid curved substrate H05K 2201/09018)	2201/0939	Curved pads, e.g. semi-circular or elliptical pads or lands
2201/09054	. . .	Raised area or protrusion of metal substrate	2201/094	Array of pads or lands differing from one another, e.g. in size, pitch, thickness; Using different connections on the pads (using different types of conductors H05K 2201/0391)
2201/09063	. . .	Holes or slots in insulating substrate not used for electrical connections	2201/09409	Multiple rows of pads, lands, terminals or dummy patterns; Multiple rows of mounted components
2201/09072	. . .	Hole or recess under component or special relationship between hole and component	2201/09418	Special orientation of pads, lands or terminals of component, e.g. radial or polygonal orientation
2201/09081	. . .	Tongue or tail integrated in planar structure, e.g. obtained by cutting from the planar structure	2201/09427	Special relation between the location or dimension of a pad or land and the location or dimension of a terminal
2201/0909	. . .	Preformed cutting or breaking line	2201/09436	Pads or lands on permanent coating which covers the other conductors
2201/091	. . .	Locally and permanently deformed areas including dielectric material	2201/09445	Pads for connections not located at the edge of the PCB, e.g. for flexible circuits
2201/09109	. . .	Locally detached layers, e.g. in multilayer	2201/09454	Inner lands, i.e. lands around via or plated through-hole in internal layer of multilayer PCB
2201/09118	. . .	Moulded substrate			
2201/09127	. . .	PCB or component having an integral separable or breakable part			
2201/09136	. . .	Means for correcting warpage			
2201/09145	. .	Edge details			
2201/09154	. . .	Bevelled, chamfered or tapered edge			
2201/09163	. . .	Slotted edge			
2201/09172	. . .	Notches between edge pads			
2201/09181	. . .	Notches in edge pads			
2201/0919	. . .	Exposing inner circuit layers or metal planes at the side edge of the PCB or at the walls of large holes (shielding provided by an inner layer of PCB H05K 2201/0723)			
2201/092	. . .	Exposing inner circuit layers or metal planes at the walls of high aspect ratio holes (forming plated-through holes H05K 3/42 ; cutting around hole H05K 2203/0242)			
2201/09209	. .	Shape and layout details of conductors			
2201/09218	. . .	Conductive traces			

- 2201/09463 Partial lands, i.e. lands or conductive rings not completely surrounding the hole ([landless plated-through hole or via H05K 2201/09545](#))
- 2201/09472 Recessed pad for surface mounting ([recess in pad H05K 2201/09745](#)); Recessed electrode of component
- 2201/09481 Via in pad; Pad over filled via ([if used for surface mounting H05K 1/113](#))
- 2201/0949 Pad close to a hole, not surrounding the hole ([if used for surface mounting H05K 1/114](#))
- 2201/095 Conductive through-holes or vias
- 2201/09509 Blind vias, i.e. vias having one side closed
- 2201/09518 Deep blind vias, i.e. blind vias connecting the surface circuit to circuit layers deeper than the first buried circuit layer
- 2201/09527 Inverse blind vias, i.e. bottoms outwards in multilayer PCB; Blind vias in centre of PCB having opposed bottoms
- 2201/09536 Buried plated through-holes, i.e. plated through-holes formed in a core before lamination
- 2201/09545 Plated through-holes or blind vias without lands
- 2201/09554 Via connected to metal substrate
- 2201/09563 Metal filled via ([plated through-hole filled with insulating material H05K 2201/0959](#))
- 2201/09572 Solder filled plated through-hole in the final product ([soldering lead-in-hole components H05K 3/3447](#))
- 2201/09581 Applying an insulating coating on the walls of holes
- 2201/0959 Plated through-holes or plated blind vias filled with insulating material
- 2201/096 Vertically aligned vias, holes or stacked vias
- 2201/09609 Via grid, i.e. two-dimensional array of vias or holes in a single plane ([interposers H05K 2201/10378](#))
- 2201/09618 Via fence, i.e. one-dimensional array of vias
- 2201/09627 Special connections between adjacent vias, not for grounding vias ([redundant conductors or connections H05K 2201/0979](#))
- 2201/09636 Details of adjacent, not connected vias
- 2201/09645 Patterning on via walls; Plural lands around one hole
- 2201/09654 covering at least two types of conductors provided for in [H05K 2201/09218](#) - [H05K 2201/095](#)
- 2201/09663 Divided layout, i.e. conductors divided in two or more parts ([branched layout H05K 2201/09254](#))
- 2201/09672 Superposed layout, i.e. in different planes ([parallel traces in one plane H05K 2201/09236](#))
- 2201/09681 Mesh conductors, e.g. as a ground plane
- 2201/0969 Apertured conductors
- 2201/097 Alternating conductors, e.g. alternating different shaped pads, twisted pairs; Alternating components
- 2201/09709 Staggered pads, lands or terminals; Parallel conductors in different planes
- 2201/09718 Clearance holes
- 2201/09727 Varying width along a single conductor; Conductors or pads having different widths
- 2201/09736 Varying thickness of a single conductor; Conductors in the same plane having different thicknesses
- 2201/09745 Recess in conductor, e.g. in pad or in metallic substrate
- 2201/09754 Connector integrally incorporated in the PCB or in housing ([mounted connector H05K 2201/10189](#))
- 2201/09763 Printed component having superposed conductors, but integrated in one circuit layer
- 2201/09772 Conductors directly under a component but not electrically connected to the component ([cooling of mounted components by printed thermal vias H05K 1/0206](#))
- 2201/09781 Dummy conductors, i.e. not used for normal transport of current; Dummy electrodes of components
- 2201/0979 Redundant conductors or connections, i.e. more than one current path between two points
- 2201/098 Special shape of the cross-section of conductors, e.g. very thick plated conductors
- 2201/09809 Coaxial layout ([reduction of cross-talk, noise or interference by printed shielding conductors for shielding around a single via or around a group of vias H05K 1/0222](#))
- 2201/09818 . . . Other shape and layout details not provided for in [H05K 2201/09009](#) - [H05K 2201/09209](#); Shape and layout details covering several of these groups
- 2201/09827 . . . Tapered, e.g. tapered hole, via or groove ([bevelled, chamfered or tapered edge H05K 2201/09154](#))
- 2201/09836 . . . Oblique hole, via or bump
- 2201/09845 . . . Stepped hole, via, edge, bump or conductor
- 2201/09854 . . . Hole or via having special cross-section, e.g. elliptical
- 2201/09863 . . . Concave hole or via
- 2201/09872 . . . Insulating conformal coating ([foil encapsulation H05K 2203/1311](#))
- 2201/09881 . . . Coating only between conductors, i.e. flush with the conductors
- 2201/0989 . . . Coating free areas, e.g. areas other than pads or lands free of solder resist
- 2201/099 . . . Coating over pads, e.g. solder resist partly over pads
- 2201/09909 . . . Special local insulating pattern, e.g. as dam around component
- 2201/09918 . . . Optically detected marks used for aligning tool relative to the PCB, e.g. for mounting of components
- 2201/09927 . . . Machine readable code, e.g. bar code
- 2201/09936 . . . Marks, inscriptions, etc. for information
- 2201/09945 . . . Universal aspects, e.g. universal inner layers or via grid, or anisotropic interposer
- 2201/09954 . . . More mounting possibilities, e.g. on same place of PCB, or by using different sets of edge pads
- 2201/09963 . . . Programming circuit by using small elements, e.g. small PCBs
- 2201/09972 . . . Partitioned, e.g. portions of a PCB dedicated to different functions; Boundary lines therefore; Portions of a PCB being processed separately or differently
- 2201/09981 . . . Metallised walls

2201/0999	. . .	Circuit printed on or in housing, e.g. housing as PCB; Circuit printed on the case of a component; PCB affixed to housing
2201/10	. .	Details of components or other objects attached to or integrated in a printed circuit board
2201/10007	. .	Types of components
2201/10015	. . .	Non-printed capacitor
2201/10022	. . .	Non-printed resistor
2201/1003	. . .	Non-printed inductor
2201/10037	. . .	Printed or non-printed battery
2201/10045	. . .	Mounted network component having plural terminals
2201/10053	. . .	Switch
2201/1006	. . .	Non-printed filter
2201/10068	. . .	Non-printed resonator
2201/10075	. . .	Non-printed oscillator
2201/10083	. . .	Electromechanical or electro-acoustic component, e.g. microphone
2201/1009	. . .	Electromotor
2201/10098	. . .	Component for radio transmission, e.g. Radio Frequency Identification Tag [RFID]
2201/10106	. . .	Light emitting diode [LED]
2201/10113	. . .	Lamp
2201/10121	. . .	Optical component, e.g. opto-electronic component
2201/10128	. . .	Display
2201/10136	. . .	Liquid Crystal display [LCD]
2201/10143	. . .	Solar cell
2201/10151	. . .	Sensor
2201/10159	. . .	Memory
2201/10166	. . .	Transistor
2201/10174	. . .	Diode
2201/10181	. . .	Fuse
2201/10189	. . .	Non-printed connector
2201/10196	. . .	Variable component, e.g. variable resistor
2201/10204	. . .	Dummy component, dummy PCB or template, e.g. for monitoring, controlling of processes, comparing, scanning
2201/10212	. . .	Programmable component
2201/10219	. . .	Thermoelectric component
2201/10227	. .	Other objects, e.g. metallic pieces
2201/10234	. . .	Metallic balls (solder balls H05K 2203/041)
2201/10242	. . .	Metallic cylinders (small solder preforms other than balls H05K 2203/0415)
2201/1025	. . .	Metallic discs (small solder preforms other than balls H05K 2203/0415)
2201/10257	. . .	Hollow pieces of metal, e.g. used in connection between component and PCB
2201/10265	. . .	Metallic coils or springs, e.g. as part of a connection element
2201/10272	. . .	Busbars, i.e. thick metal bars mounted on the PCB as high-current conductors (metal strips H05K 2201/1028)
2201/1028	. . .	Thin metal strips as connectors or conductors
2201/10287	. . .	Metal wires as connectors or conductors
2201/10295	. . .	Metallic connector elements partly mounted in a hole of the PCB
2201/10303	. . .	Pin-in-hole mounted pins
2201/1031	. . .	Surface mounted metallic connector elements
2201/10318	. . .	Surface mounted metallic pins
2201/10325	. . .	Sockets, i.e. female type connectors comprising metallic connector elements integrated in, or bonded to a common dielectric support
2201/10333	. . .	Individual female type metallic connector elements
2201/1034	. . .	Edge terminals, i.e. separate pieces of metal attached to the edge of the PCB (tab H05K 2201/0397)
2201/10348	. . .	Fuzz's as connector elements, i.e. small pieces of metallic fiber to make connection
2201/10356	. . .	Cables
2201/10363	. . .	Jumpers, i.e. non-printed cross-over connections
2201/10371	. . .	Shields or metal cases
2201/10378	. . .	Interposers
2201/10386	. . .	Clip leads; Terminals gripping the edge of a substrate
2201/10393	. . .	Clamping a component by an element or a set of elements
2201/10401	. . .	Eyelets, i.e. rings inserted into a hole through a circuit board
2201/10409	. . .	Screws
2201/10416	. . .	Metallic blocks or heatsinks completely inserted in a PCB (metallic supports H05K 3/0061)
2201/10424	. . .	Frame holders
2201/10431	. . .	Details of mounted components (printed components H05K 1/16)
2201/10439	. . .	Position of a single component
2201/10446	. . .	Mounted on an edge (soldering edge mounted components H05K 3/3405 ; edge terminals H05K 2201/1034)
2201/10454	. . .	Vertically mounted
2201/10462	. . .	Flat component oriented parallel to the PCB surface
2201/10469	. . .	Asymmetrically mounted component
2201/10477	. . .	Inverted
2201/10484	. . .	Obliquely mounted
2201/10492	. . .	Electrically connected to another device (mounted components directly electrically connected to each other H05K 2201/1053)
2201/105	. . .	Mechanically attached to another device (attached components H05K 2201/10537)
2201/10507	. . .	Involving several components
2201/10515	. . .	Stacked components
2201/10522	. . .	Adjacent components
2201/1053	. . .	Mounted components directly electrically connected to each other, i.e. not via the PCB
2201/10537	. . .	Attached components
2201/10545	. . .	Related components mounted on both sides of the PCB
2201/10553	. . .	Component over metal, i.e. metal plate in between bottom of component and surface of PCB
2201/1056	. . .	Metal over component, i.e. metal plate over component mounted on or embedded in PCB
2201/10568	. . .	Integral adaptations of a component or an auxiliary PCB for mounting, e.g. integral spacer element
2201/10575	. . .	Insulating foil under component (permanent spacer or stand-off H05K 2201/2036)
2201/10583	. . .	Cylindrically shaped component; Fixing means therefore
2201/1059	. . .	Connections made by press-fit insertion
2201/10598	. . .	Means for fastening a component, a casing or a heat sink whereby a pressure is exerted on the component towards the PCB

- 2201/10606 . . . Permanent holder for component or auxiliary PCB mounted on a PCB ([clamping a component by an element or a set of elements H05K 2201/10393](#))
- 2201/10613 . . Details of electrical connections of non-printed components, e.g. special leads
- 2201/10621 . . . Components characterised by their electrical contacts
- 2201/10628 Leaded surface mounted device ([soldering surface mounted leaded components H05K 3/3421](#))
- 2201/10636 Leadless chip, e.g. chip capacitor or resistor
- 2201/10643 Disc shaped leadless component
- 2201/10651 Component having two leads, e.g. resistor, capacitor
- 2201/10659 Different types of terminals for the same component, e.g. solder balls combined with leads
- 2201/10666 Plated through-hole for surface mounting on PCB
- 2201/10674 Flip chip
- 2201/10681 Tape Carrier Package [TCP]; Flexible sheet connector
- 2201/10689 Leaded Integrated Circuit [IC] package, e.g. dual-in-line [DIL]
- 2201/10696 Single-in-line [SIL] package
- 2201/10704 Pin grid array [PGA]
- 2201/10712 Via grid array, e.g. via grid array capacitor
- 2201/10719 Land grid array [LGA]
- 2201/10727 Leadless chip carrier [LCC], e.g. chip-modules for cards
- 2201/10734 Ball grid array [BGA]; Bump grid array
- 2201/10742 . . . Details of leads
- 2201/1075 Shape details
- 2201/10757 Bent leads
- 2201/10765 Leads folded back, i.e. bent with an angle of 180 deg
- 2201/10772 Leads of a surface mounted component bent for providing a gap between the lead and the pad during soldering
- 2201/1078 Leads having locally deformed portion, e.g. for retention
- 2201/10787 Leads having protrusions, e.g. for retention or insert stop
- 2201/10795 Details of lead tips, e.g. pointed
- 2201/10803 Tapered leads, i.e. leads having changing width or diameter
- 2201/1081 Special cross-section of a lead; Different cross-sections of different leads; Matching cross-section, e.g. matched to a land
- 2201/10818 Flat leads
- 2201/10825 Distorted or twisted flat leads, i.e. deformed by torque
- 2201/10833 having a curved or folded cross-section
- 2201/1084 Notched leads
- 2201/10848 Thinned leads
- 2201/10856 Divided leads, e.g. by slot in length direction of lead, or by branching of the lead
- 2201/10863 Adaptations of leads or holes for facilitating insertion
- 2201/10871 Leads having an integral insert stop
- 2201/10878 Means for retention of a lead in a hole
- 2201/10886 Other details
- 2201/10893 Grouped leads, i.e. element comprising multiple leads distributed around but not through a common insulator
- 2201/10901 Lead partly inserted in hole or via
- 2201/10909 Materials of terminal, e.g. of leads or electrodes of components
- 2201/10916 Terminals having auxiliary metallic piece, e.g. for soldering
- 2201/10924 Leads formed from a punched metal foil ([affixing a prefabricated self-supporting metal foil pattern H05K 3/202](#))
- 2201/10931 Exposed leads, i.e. encapsulation of component partly removed for exposing a part of lead, e.g. for soldering purposes
- 2201/10939 Lead of component used as a connector
- 2201/10946 Leads attached onto leadless component after manufacturing the component
- 2201/10954 . . . Other details of electrical connections
- 2201/10962 Component not directly connected to the PCB
- 2201/10969 Metallic case or integral heatsink of component electrically connected to a pad on PCB
- 2201/10977 Encapsulated connections ([applying non-metallic protective coatings for encapsulating mounted components H05K 3/284](#))
- 2201/10984 Component carrying a connection agent, e.g. solder, adhesive ([soldering leadless components having an array of bottom contacts H05K 3/3436](#); [BGA components H05K 2201/10734](#))
- 2201/10992 Using different connection materials, e.g. different solders, for the same connection
- 2201/20 . . Details of printed circuits not provided for in [H05K 2201/01](#) - [H05K 2201/10](#)
- 2201/2009 . . Reinforced areas, e.g. for a specific part of a flexible printed circuit
- 2201/2018 . . Presence of a frame in a printed circuit or printed circuit assembly
- 2201/2027 . . Guiding means, e.g. for guiding flexible circuits
- 2201/2036 . . Permanent spacer or stand-off in a printed circuit or printed circuit assembly ([pattern for applying drops or paste H05K 2203/0545](#))
- 2201/2045 . . Protection against vibrations
- 2201/2054 . . Light-reflecting surface, e.g. conductors, substrates, coatings, dielectrics
- 2201/2063 . . mixed adhesion layer containing metallic/inorganic and polymeric materials
- 2201/2072 . . Anchoring, i.e. one structure gripping into another ([providing micro- or nanometer scale roughness on a metal surface H05K 2203/0307](#))
- 2201/2081 . . Compound repelling a metal, e.g. solder
- 2201/209 . . Auto-mechanical connection between a component and a PCB or between two PCBs
- 2203/00 Indexing scheme relating to apparatus or processes for manufacturing printed circuits covered by [H05K 3/00](#)**
- 2203/01 . . Tools for processing; Objects used during processing
- 2203/0104 . . for patterning or coating
- 2203/0108 . . Male die used for patterning, punching or transferring

- 2203/0113 . . . Female die used for patterning or transferring, e.g. temporary substrate having recessed pattern
- 2203/0117 . . . Pattern shaped electrode used for patterning, e.g. plating or etching
- 2203/0121 . . . Patterning, e.g. plating or etching by moving electrode
- 2203/0126 . . . Dispenser, e.g. for solder paste, for supplying conductive paste for screen printing or for filling holes
- 2203/013 . . . Inkjet printing, e.g. for printing insulating material or resist ([using ink-jet printing to form a conductive pattern H05K 3/125](#))
- 2203/0134 . . . Drum, e.g. rotary drum or dispenser with a plurality of openings
- 2203/0139 . . . Blade or squeegee, e.g. for screen printing or filling of holes
- 2203/0143 . . . Using a roller; Specific shape thereof; Providing locally adhesive portions thereon
- 2203/0147 . . . Carriers and holders
- 2203/0152 . . . Temporary metallic carrier, e.g. for transferring material ([affixing a prefabricated conductor pattern formed by electroplating or electroforming on a metallic carrier H05K 3/205](#))
- 2203/0156 . . . Temporary polymeric carrier or foil, e.g. for processing or transferring
- 2203/016 . . . Temporary inorganic, non-metallic carrier, e.g. for processing or transferring
- 2203/0165 . . . Holder for holding a Printed Circuit Board [PCB] during processing, e.g. during screen printing
- 2203/0169 . . . Using a temporary frame during processing
- 2203/0173 . . . Template for holding a PCB having mounted components thereon
- 2203/0178 . . . Projectile, e.g. for perforating substrate
- 2203/0182 . . . Using a temporary spacer element or stand-off during processing
- 2203/0186 . . . Mask formed or laid on PCB, the mask having recesses or openings specially designed for mounting components or body parts thereof
- 2203/0191 . . . Using tape or non-metallic foil in a process, e.g. during filling of a hole with conductive paste
- 2203/0195 . . . Tool for a process not provided for in [H05K 3/00](#), e.g. tool for handling objects using suction, for deforming objects, for applying local pressure
- 2203/02 . . . Details related to mechanical or acoustic processing, e.g. drilling, punching, cutting, using ultrasound
- 2203/0207 . . . Partly drilling through substrate until a controlled depth, e.g. with end-point detection
- 2203/0214 . . . Back-up or entry material, e.g. for mechanical drilling
- 2203/0221 . . . Perforating
- 2203/0228 . . . Cutting, sawing, milling or shearing
- 2203/0235 . . . Laminating followed by cutting or slicing perpendicular to plane of the laminate; Embedding wires in an object and cutting or slicing the object perpendicular to direction of the wires
- 2203/0242 . . . Cutting around hole, e.g. for disconnecting land or Plated Through-Hole [PTH] or for partly removing a PTH
- 2203/025 . . . Abrading, e.g. grinding or sand blasting ([deburring, rounding, bevelling or smoothing conductor edges H05K 2203/0346](#))
- 2203/0257 . . . Brushing, e.g. cleaning the conductive pattern by brushing or wiping
- 2203/0264 . . . Peeling insulating layer, e.g. foil, or separating mask
- 2203/0271 . . . Mechanical force other than pressure, e.g. shearing or pulling
- 2203/0278 . . . Flat pressure, e.g. for connecting terminals with anisotropic conductive adhesive
- 2203/0285 . . . Using ultrasound, e.g. for cleaning, soldering or wet treatment
- 2203/0292 . . . Using vibration, e.g. during soldering or screen printing
- 2203/03 . . . Metal processing
- 2203/0307 . . . Providing micro- or nanometer scale roughness on a metal surface, e.g. by plating of nodules or dendrites
- 2203/0315 . . . Oxidising metal
- 2203/0323 . . . Working metal substrate or core, e.g. by etching, deforming
- 2203/033 . . . Punching metal foil, e.g. solder foil ([affixing a prefabricated self-supporting metal foil pattern H05K 3/202](#))
- 2203/0338 . . . Transferring metal or conductive material other than a circuit pattern, e.g. bump, solder, printed component ([affixing a prefabricated conductor pattern H05K 3/20](#))
- 2203/0346 . . . Deburring, rounding, bevelling or smoothing conductor edges
- 2203/0353 . . . Making conductive layer thin, e.g. by etching ([selective thinning for providing different thickness H05K 2203/0369](#))
- 2203/0361 . . . Stripping a part of an upper metal layer to expose a lower metal layer, e.g. by etching or using a laser
- 2203/0369 . . . Etching selective parts of a metal substrate through part of its thickness, e.g. using etch resist
- 2203/0376 . . . Etching temporary metallic carrier substrate
- 2203/0384 . . . Etch stop layer, i.e. a buried barrier layer for preventing etching of layers under the etch stop layer
- 2203/0392 . . . Pretreatment of metal, e.g. before finish plating, etching ([improvement of the adhesion between an insulating substrate and a metal by special treatment of the metal H05K 3/382](#))
- 2203/04 . . . Soldering or other types of metallurgic bonding ([using molten metal H05K 2203/128](#))
- 2203/0405 . . . Solder foil, tape or wire
- 2203/041 . . . Solder preforms in the shape of solder balls ([soldering leadless components having an array of bottom contacts H05K 3/3436](#))
- 2203/0415 . . . Small preforms other than balls, e.g. discs, cylinders or pillars
- 2203/042 . . . Remote solder depot on the PCB, the solder flowing to the connections from this depot
- 2203/0425 . . . Solder powder or solder coated metal powder
- 2203/043 . . . Reflowing of solder coated conductors, not during connection of components, e.g. reflowing solder paste
- 2203/0435 . . . Metal coated solder, e.g. for passivation of solder balls

- 2203/044 . . Solder dip coating, i.e. coating printed conductors, e.g. pads by dipping in molten solder or by wave soldering
- 2203/0445 . . Removing excess solder on pads; removing solder bridges, e.g. for repairing or reworking
- 2203/045 . . Solder filled PTH during processing ([solder filled plated through-hole in the final product H05K 2201/09572](#))
- 2203/0455 . . PTH for surface mount device [SMD], e.g. wherein solder flows through the PTH during mounting
- 2203/046 . . Means for drawing solder, e.g. for removing excess solder from pads
- 2203/0465 . . Shape of solder, e.g. differing from spherical shape, different shapes due to different solder pads
- 2203/047 . . Soldering with different solders, e.g. two different solders on two sides of the PCB
- 2203/0475 . . Molten solder just before placing the component
- 2203/048 . . Self-alignment during soldering; Terminals, pads or shape of solder adapted therefor
- 2203/0485 . . Tacky flux, e.g. for adhering components during mounting
- 2203/049 . . Wire bonding
- 2203/0495 . . Cold welding
- 2203/05 . . Patterning and lithography; Masks; Details of resist
- 2203/0502 . . Patterning and lithography
- 2203/0505 . . . Double exposure of the same photosensitive layer
- 2203/0508 . . . Flood exposure
- 2203/0511 . . . Diffusion patterning
- 2203/0514 . . . Photodevelopable thick film, e.g. conductive or insulating paste
- 2203/0517 . . . Electrographic patterning
- 2203/052 . . . Magnetographic patterning
- 2203/0522 . . . Using an adhesive pattern
- 2203/0525 . . . Patterning by phototackifying or by photopatterning adhesive
- 2203/0528 . . . Patterning during transfer, i.e. without preformed pattern, e.g. by using a die, a programmed tool or a laser
- 2203/0531 . . . Decalomania, i.e. transfer of a pattern detached from its carrier before affixing the pattern to the substrate
- 2203/0534 . . . Offset printing, i.e. transfer of a pattern from a carrier onto the substrate by using an intermediate member
- 2203/0537 . . . Transfer of pre-fabricated insulating pattern
- 2203/054 . . . Continuous temporary metal layer over resist, e.g. for selective electroplating
- 2203/0542 . . . Continuous temporary metal layer over metal pattern ([reinforcing the conductive pattern characterised by the electroplating method H05K 3/241](#))
- 2203/0545 . . . Pattern for applying drops or paste; Applying a pattern made of drops or paste ([using thick film techniques to apply conductive material by using a substrate with a shape pattern H05K 3/1258](#))
- 2203/0548 . . Masks
- 2203/0551 . . . Exposure mask directly printed on the PCB
- 2203/0554 . . . Metal used as mask for etching vias, e.g. by laser ablation
- 2203/0557 . . . Non-printed masks
- 2203/056 . . . Using an artwork, i.e. a photomask for exposing photosensitive layers
- 2203/0562 . . Details of resist
- 2203/0565 . . . Resist used only for applying catalyst, not for plating itself
- 2203/0568 . . . Resist used for applying paste, ink or powder
- 2203/0571 . . . Dual purpose resist, e.g. etch resist used as solder resist, solder resist used as plating resist
- 2203/0574 . . . Stacked resist layers used for different processes
- 2203/0577 . . . Double layer of resist having the same pattern
- 2203/058 . . . Additional resists used for the same purpose but in different areas, i.e. not stacked
- 2203/0582 . . . Coating by resist, i.e. resist used as mask for application of insulating coating or of second resist
- 2203/0585 . . . Second resist used as mask for selective stripping of first resist
- 2203/0588 . . . Second resist used as pattern over first resist
- 2203/0591 . . . Organic non-polymeric coating, e.g. for inhibiting corrosion thereby preserving solderability
- 2203/0594 . . . Insulating resist or coating with special shaped edges
- 2203/0597 . . . Resist applied over the edges or sides of conductors, e.g. for protection during etching or plating ([coating over pads H05K 2201/09818](#))
- 2203/06 . . Lamination
- 2203/061 . . of previously made multilayered subassemblies ([laminating only or mainly similar single-sided circuit boards H05K 3/4617](#); [laminating only or mainly similar double-sided circuit boards H05K 3/462](#))
- 2203/063 . . of preperforated insulating layer
- 2203/065 . . Binding insulating layers without adhesive, e.g. by local heating or welding, before lamination of the whole PCB
- 2203/066 . . Transfer laminating of insulating material, e.g. resist as a whole layer, not as a pattern ([transferring an insulating pattern H05K 2203/0537](#))
- 2203/068 . . Features of the lamination press or of the lamination process, e.g. using special separator sheets
- 2203/07 . . Treatments involving liquids, e.g. plating, rinsing
- 2203/0703 . . Plating
- 2203/0706 . . . Inactivating or removing catalyst, e.g. on surface of resist
- 2203/0709 . . . Catalytic ink or adhesive for electroless plating ([catalyst filler H05K 2201/0236](#))
- 2203/0713 . . . Plating poison, e.g. for selective plating or for preventing plating on resist
- 2203/0716 . . . Metallic plating catalysts, e.g. for direct electroplating of through holes; Sensitising or activating metallic plating catalysts
- 2203/072 . . . Electroless plating, e.g. finish plating or initial plating
- 2203/0723 . . . Electroplating, e.g. finish plating
- 2203/0726 . . . Electroforming, i.e. electroplating on a metallic carrier thereby forming a self-supporting structure
- 2203/073 . . . Displacement plating, substitution plating or immersion plating, e.g. for finish plating

- 2203/0733 . . . Method for plating stud vias, i.e. massive vias formed by plating the bottom of a hole without plating on the walls
- 2203/0736 . . . Methods for applying liquids, e.g. spraying
- 2203/074 . . . Features related to the fluid pressure
- 2203/0743 . . . Mechanical agitation of fluid, e.g. during cleaning of the conductive pattern
- 2203/0746 . . . Local treatment using a fluid jet, e.g. for removing or cleaning material; Providing mechanical pressure using a fluid jet
- 2203/075 . . . Global treatment of printed circuits by fluid spraying, e.g. cleaning a conductive pattern using nozzles
- 2203/0753 . . . Reversing fluid direction, e.g. in holes
- 2203/0756 . . . Uses of liquids, e.g. rinsing, coating, dissolving
- 2203/0759 . . . Forming a polymer layer by liquid coating, e.g. a non-metallic protective coating or an organic bonding layer
- 2203/0763 . . . Treating individual holes or single row of holes, e.g. by nozzle
- 2203/0766 . . . Rinsing, e.g. after cleaning or polishing a conductive pattern
- 2203/0769 . . . Dissolving insulating materials, e.g. coatings, not used for developing resist after exposure
- 2203/0773 . . . Dissolving the filler without dissolving the matrix material; Dissolving the matrix material without dissolving the filler
- 2203/0776 . . . Uses of liquids not otherwise provided for in [H05K 2203/0759](#) - [H05K 2203/0773](#)
- 2203/0779 . . . characterised by the specific liquids involved
- 2203/0783 . . . Using solvent, e.g. for cleaning; Regulating solvent content of pastes or coatings for adjusting the viscosity
- 2203/0786 . . . Using an aqueous solution, e.g. for cleaning or during drilling of holes
- 2203/0789 Aqueous acid solution, e.g. for cleaning or etching
- 2203/0793 Aqueous alkaline solution, e.g. for cleaning or etching
- 2203/0796 Oxidant in aqueous solution, e.g. permanganate
- 2203/08 . . . Treatments involving gases
- 2203/081 . . . Blowing of gas, e.g. for cooling or for providing heat during solder reflowing
- 2203/082 . . . Suction, e.g. for holding solder balls or components
- 2203/083 . . . Evaporation or sublimation of a compound, e.g. gas bubble generating agent
- 2203/085 . . . Using vacuum or low pressure
- 2203/086 . . . Using an inert gas
- 2203/087 . . . Using a reactive gas
- 2203/088 . . . Using a vapour or mist, e.g. cleaning using water vapor
- 2203/09 . . . Treatments involving charged particles
- 2203/092 . . . Particle beam, e.g. using an electron beam or an ion beam
- 2203/095 . . . Plasma, e.g. for treating a substrate to improve adhesion with a conductor or for cleaning holes
- 2203/097 Corona discharge
- 2203/10 . . . Using electric, magnetic and electromagnetic fields; Using laser light
- 2203/101 . . . Using electrical induction, e.g. for heating during soldering
- 2203/102 . . . Using microwaves, e.g. for curing ink patterns or adhesive
- 2203/104 . . . Using magnetic force, e.g. to align particles or for a temporary connection during processing
- 2203/105 . . . Using an electrical field; Special methods of applying an electric potential ([electroplating H05K 2203/0723](#))
- 2203/107 . . . Using laser light ([shaping a substrate by laser ablation H05K 3/0026](#))
- 2203/108 Using a plurality of lasers or laser light with a plurality of wavelengths
- 2203/11 . . . Treatments characterised by their effect, e.g. heating, cooling, roughening
- 2203/1105 . . . Heating or thermal processing not related to soldering, firing, curing or laminating, e.g. for shaping the substrate or during finish plating
- 2203/111 . . . Preheating, e.g. before soldering
- 2203/1115 . . . Resistance heating, e.g. by current through the PCB conductors or through a metallic mask
- 2203/1121 . . . Cooling, e.g. specific areas of a PCB being cooled during reflow soldering ([details related to cooling of mounted components H05K 1/0203](#))
- 2203/1126 . . . Firing, i.e. heating a powder or paste above the melting temperature of at least one of its constituents
- 2203/1131 . . . Sintering, i.e. fusing of metal particles to achieve or improve electrical conductivity
- 2203/1136 . . . Conversion of insulating material into conductive material, e.g. by pyrolysis
- 2203/1142 . . . Conversion of conductive material into insulating material or into dissolvable compound
- 2203/1147 . . . Sealing or impregnating, e.g. of pores
- 2203/1152 . . . Replicating the surface structure of a sacrificial layer, e.g. for roughening
- 2203/1157 . . . Using means for chemical reduction
- 2203/1163 . . . Chemical reaction, e.g. heating solder by exothermic reaction ([oxidising metal H05K 2203/0315](#))
- 2203/1168 . . . Graft-polymerization
- 2203/1173 . . . Differences in wettability, e.g. hydrophilic or hydrophobic areas
- 2203/1178 . . . Means for venting or for letting gases escape
- 2203/1184 . . . Underetching, e.g. etching of substrate under conductors or etching of conductor under dielectrics; Means for allowing or controlling underetching
- 2203/1189 . . . Pressing leads, bumps or a die through an insulating layer
- 2203/1194 . . . Thermal treatment leading to a different chemical state of a material, e.g. annealing for stress-relief, aging
- 2203/12 . . . Using specific substances
- 2203/121 . . . Metallo-organic compounds
- 2203/122 . . . Organic non-polymeric compounds, e.g. oil, wax, thiol ([using solvent H05K 2203/0783](#))
- 2203/124 Heterocyclic organic compounds, e.g. azole, furan
- 2203/125 . . . Inorganic compounds, e.g. silver salt
- 2203/127 . . . Lubricants, e.g. during drilling of holes
- 2203/128 . . . Molten metals, e.g. casting thereof, or melting by heating and excluding molten solder ([spraying droplets of molten metal H05K 2203/1344](#))
- 2203/13 . . . Moulding and encapsulation; Deposition techniques; Protective layers

2203/1305	. . Moulding and encapsulation	2203/1545	. . Continuous processing, i.e. involving rolls moving a band-like or solid carrier along a continuous production path
2203/1311	. . . Foil encapsulation, e.g. of mounted components	2203/1554	. . Rotating or turning the PCB in a continuous manner
2203/1316	. . . Moulded encapsulation of mounted components	2203/1563	. . Reversing the PCB
2203/1322	. . . Encapsulation comprising more than one layer	2203/1572	. . Processing both sides of a PCB by the same process; Providing a similar arrangement of components on both sides; Making interlayer connections from two sides
2203/1327	. . . Moulding over PCB locally or completely (applying non-metallic protective coatings for encapsulating mounted components H05K 3/284)	2203/1581	. . Treating the backside of the PCB, e.g. for heating during soldering or providing a liquid coating on the backside
2203/1333	. . Deposition techniques, e.g. coating	2203/159	. . Using gravitational force; Processing against the gravity direction; Using centrifugal force
2203/1338	. . . Chemical vapour deposition	2203/16	. . Inspection; Monitoring; Aligning
2203/1344	. . . Spraying small metal particles or droplets of molten metal	2203/161	. . Using chemical substances, e.g. colored or fluorescent, for facilitating optical or visual inspection
2203/135	. . . Electrophoretic deposition of insulating material	2203/162	. . Testing a finished product, e.g. heat cycle testing of solder joints (patterns for electrical inspection or testing H05K 1/0268)
2203/1355	. . . Powder coating of insulating material	2203/163	. . Monitoring a manufacturing process
2203/1361	. . . Coating by immersion in coating bath (applying molten solder H05K 3/3468)	2203/165	. . Stabilizing, e.g. temperature stabilization
2203/1366	. . . Spraying coating (apparatus for coating printed circuit boards using liquid non-metallic coating compositions H05K 3/0091)	2203/166	. . Alignment or registration; Control of registration
2203/1372	. . . Coating by using a liquid wave (solder dip coating H05K 2203/04)	2203/167	. . Using mechanical means for positioning, alignment or registration, e.g. using rod-in-hole alignment
2203/1377	. . Protective layers	2203/168	. . Wrong mounting prevention
2203/1383	. . . Temporary protective insulating layer	2203/17	. . Post-manufacturing processes
2203/1388	. . . Temporary protective conductive layer	2203/171	. . Tuning, e.g. by trimming of printed components or high frequency circuits
2203/1394	. . . Covering open PTHs, e.g. by dry film resist or by metal disc	2203/173	. . Adding connections between adjacent pads or conductors, e.g. for modifying or repairing (programmable, customizable or modifiable circuits H05K 1/0286)
2203/14	. Related to the order of processing steps	2203/175	. . Configurations of connections suitable for easy deletion, e.g. modifiable circuits or temporary conductors for electroplating; Processes for deleting connections
2203/1407	. . Applying catalyst before applying plating resist	2203/176	. . Removing, replacing or disconnecting component; Easily removable component (thermal arrangements, e.g. to prevent overheating H05K 1/0201)
2203/1415	. . Applying catalyst after applying plating resist	2203/178	. . Demolishing, e.g. recycling, reverse engineering, destroying for security purposes; Using biodegradable materials
2203/1423	. . Applying catalyst before etching, e.g. plating catalyst in holes before etching circuit	2203/30	. . Details of processes not otherwise provided for in H05K 2203/01 - H05K 2203/17
2203/143	. . Treating holes before another process, e.g. coating holes before coating the substrate	2203/302	. . Bending a rigid substrate; Breaking rigid substrates by bending (rigid circuit boards or rigid supports locally made bendable H05K 1/0278)
2203/1438	. . Treating holes after another process, e.g. coating holes after coating the substrate (metal used as mask for etching vias H05K 2203/0554)	2203/304	. . Protecting a component during manufacturing
2203/1446	. . Treatment after insertion of lead into hole, e.g. bending, cutting, caulking or curing of adhesive but excluding soldering	2203/306	. . Lifting the component during or after mounting; Increasing the gap between component and PCB
2203/1453	. . Applying the circuit pattern before another process, e.g. before filling of vias with conductive paste, before making printed resistors	2203/308	. . Sacrificial means, e.g. for temporarily filling a space for making a via or a cavity or for making rigid-flexible PCBs
2203/1461	. . Applying or finishing the circuit pattern after another process, e.g. after filling of vias with conductive paste, after making printed resistors		
2203/1469	. . . Circuit made after mounting or encapsulation of the components		
2203/1476	. . Same or similar kind of process performed in phases, e.g. coarse patterning followed by fine patterning		
2203/1484	. . Simultaneous treatments, e.g. soldering lead-in-hole components simultaneously with surface mounted components		
2203/1492	. . Periodical treatments, e.g. pulse plating of through-holes		
2203/15	. Position of the PCB during processing		
2203/1509	. . Horizontally held PCB		
2203/1518	. . Vertically held PCB		
2203/1527	. . Obliquely held PCB		
2203/1536	. . Temporarily stacked PCBs		
		Dummy groups for the purpose of scheme testing, logistics of documents or the like	
		999/00	dummy group
			WARNING

H05K 999/00

(continued)

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